



## September 11-14, 2017 Leuven, Belgium

## **ESSCIRC**

43<sup>rd</sup> European Solid-State Circuits Conference

Organized by









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A world leader in automotive semiconductor sensors, Melexis has used its core experience in creating chips for vehicle electronics to expand its portfolio of sensors, driver ICs and wireless devices to also meet the needs of smart appliances, home automation, industrial and medical applications. Melexis sensing solutions include magnetic sensors, MEMS sensors (pressure, TPMS, infrared), sensor interface ICs, optoelectronic single point and linear array sensors and Time of Flight. The company's driver IC portfolio incorporates advanced DC & BLDC motor controllers, LED drivers and FET pre-driver ICs, while Melexis has the know-how and expertise to build bridges between components, allowing them to communicate in a clear and fast way, whether wired (e.g. LIN, SENT) or wireless (RKE, RFID).

Melexis is headquartered in Belgium and employs over 1,100 people in 19 locations worldwide. The company is publicly traded on Euronext Brussels (MELE).

For more information, visit www.melexis.com

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On behalf of the entire Organizing Committee, it is our pleasure to welcome you to the 47th European Solid-State Device Research Conference (ESSDERC) and the 43rd European Solid-State Circuits Conference (ESSCIRC) 2017. ESSDERC-ESSCICRC finally returns back to the university town of Leuven, Belgium, many years after having organised a successful ESSDERC-ESSCIRC Conference in 2004 and ESSDERC Conferences in 1999 and 1992, respectively. Since 2003 both ESSDERC and ESSCIRC are running in parallel and have joint keynote speakers and joint focus sessions. The increasing level of integration for system-on-chip design made available by advances in semiconductor technology is, more than ever before, calling for a deeper interaction among technologists, device experts, IC designers and system designers. As participant to ESSDERC and ESSCIRC, you not only have the opportunity to become familiar with the latest advances in these fields, but you will meet people who pioneered previous developments, you get access to enhance your international network in micro/nanoelectronics and you will be a witness to previews into emerging fields.

The conference takes place downtown in the city of Leuven, which up to the end of the 13rd century the residence of the Dukes of Brabant. Today Leuven is still the capital of the province of Flemish Brabant. Since 1425 Leuven is the home of KU Leuven, with its  $\sim\!56000$  students the largest university in Belgium. The majority of these students reside in Leuven, and this includes 16% international students. The presence of imec, the largest independent research center in Europe with over 3500 researchers coming from more than 70 different countries, brands Leuven as a world leading hub for micro- and nano-electronics.

This year ESSDERC-ESSCIRC received a total of 393 submissions from 36 countries, of which 241 contributed ESSCIRC and 153 contributed and track invited ESSDERC submissions. About 52% of the submissions came from Europe, 28% from Asia/Pacific and 18% from North America, clearly demonstrating the international character of the conference.

The conference has 4 plenary keynote speakers (Melexis, ON Semiconductor, Analog Devices and Tohoku University), 3 ESSDERC plenary speakers (Intel, SanDisk and RWTH Aachen) and 3 ESSCIRC plenary speakers (Nokia Bell Labs, Ericsson and Columbia University). The selected papers are presented in 43 regular sessions and two focus sessions on Neuromorphic Computing and Quantum Computing, respectively. All this is spread over three days of oral presentations, Tuesday September 12 to Thursday September 14.

The program also includes an extraordinary social program with a welcome reception and a conference banquet, both with surprise acts. These social events will offer ample opportunities for networking.

In addition, the first day of the event on Monday September 11 will be dedicated to 5 tutorials (1 full-day and 2 half-day tutorials organized by ESSDERC and 2 full-day tutorials organized by ESSCIRC) and to 4 workshops, organized by European and international research and industry consortia. These give extra opportunities for update your knowledge of the state of the art in the covered areas

We thank the IEEE Solid-State Circuits Society (SSCS) and the IEEE Electron Devices Society (EDS) that are the official sponsors of ESSCIRC and ESDERC, respectively. We also thank all external sponsors that have provided the extra means allowing us to offer the little extras that beyond doubt will make ESSDERC-ESSCIRC 2017 a memorable event in a long tradition.

We are very grateful to the excellent collaboration with the exceptional members of the Organizing Committee and the Technical Program Committee. All members have extremely been devoted and have worked very hard to make ESSDERC-ESSCIRC 2017 yet another successful event. Without their dedication, enthusiasm and professionalism this would not have been possible. We also thank all collaborators and volunteers that helped us out.

Finally, the real success of a conference is based on the support of all the authors who submitted papers to the conference and on the willingness of the keynote, invited, focus session and tutorial speakers to travel to Leuven and to share their knowledge and insights. Their support and efforts are highly appreciated.

Enjoy the 2017 edition of ESSDERC-ESSCIRC and your visit to Leuven, Belgium, and after enjoying and savoring this year's program, we hope to see you all again in Dresden, Germany, for ESSDERC-ESSCIRC 2018.

Jo De Boeck and Georges Gielen Conference General Chairs – ESSDERC-ESSCIRC 2017

> Marc Heyns and Guido Groeseneken TPC Chairs – ESSDERC 2017

Wim Dehaene and Patrick Reynaert TPC Chairs – ESSCIRC 2017

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- Anil Kottantharayil IIT Bombay, IN
- Maasaki Niwa Tohoku University, JP

#### **ESSCIRC TECHNICAL PROGRAM COMMITTEE**

## Track 8: Analog

- Peter Mole INTERSIL
- Pieter Harpe TU Eindhoven

Track Chair Deputy Chair

- Marco Berkhout NXP
- Stefano D'Amico University of Salento
- Marcello De Matteis University of Milano Bicocca
- Gunhan Dündar Boğaziçi University
- Kimmo Koli ERICSSON
- Salvatore Pennisi DIEEI-University of Catania
- Willy Sansen KU Leuven
- Douglas Smith Consultant
- Hugo Veenstra PHILIPS
- Traian Visan Infineon
- Andreo Vladimirescu Berkeley University

#### Track 9: Data Converters

- Andrea Baschirotto University of Milan-Bicocca Track Chair
- Dieter Draxelmayr Infineon

Deputy Chair

- Mario Auer TU Graz
- Lucien Breems NXP
- Klaas Bult Indipendent Consultant
- Claudius Dan University POLITEHNICA of Bucharest
- Michael Flynn University Michigan
- Kofi Makinwa TU Delft
- Piero Malcovati University of Pavia
- Franco Maloberti University of Pavia
- Angelo Nagari STMicroelectronics
- Maurits Ortmanns University of Ulm
- Georgi Radulov TU Eindhoven
- Ana Rusu KTM
- Jens Sauerbrey Intel
- Trond Ytterdal Norwegian University of Science and Technology

#### Track 10: RF and mm-wave

- Domine Leenaerts NXP
- Piet Wambacq imec

Track Chair Deputy Chair

- Amin Arbabian Stanford University
- Andreia Cathelin STMicroelectronics
- Mak Elvis University of Macau
- Bram Nauta University of Twente

- Andrea Neviani University of Padova
- Francois Rivet University of Bordeaux
- David Ruffieux CSEM
- Jussi Ryynänen TU Helsinki
- Kaushik Sengupta Princeton University
- Lars Sundström ERICSSON
- Marc Tiebout Infineon
- Domenico Zito Aarhus university

## Track 11: Frequency Generation

- Pietro Andreani Lunds University
- Andrea Bevilacqua University of Padova
- Deputy Chair

Track Chair

- Jaehyouk Choi Ulsan National University (UNIST)
- Martin Flatscher Infineon
- Peter Kennedy University College Cork
- Antonio Liscidini University of Toronto
- Baudouin Martineau CEA
- Kenichi Okada Tokyo Institute of Technology
- Carlo Samori Politecnico di Milano
- Alexandre Siligaris CEA
- Bogdan Staszewski UC Dublin
- Francesco Svelto University of Pavia

## Track 12: Wireless and wireline systems

Sven Mattisson - FRICSSON

- Track Chair
- Deputy Chair
- Jean Baptiste Begueret University of Bordeaux
- Didier Belot CEA-LETI

Jan Craninckx - imec

- Marc Borremans Huawei
- Giuseppe Gramegna Huawei
- Qiuting Huang ETH Zürich
- Andrea Mazzanti University of Pavia
- Dominique Morche CEA
- Takashi Oshima HITACHI
- Yorgos Palaskas Intel
- Silvian Spiridon Broadcom
- Filip Tavernier KU Leuven
- Thomas Toifl IBM
- Dixian Zhao SouthEast Universiy
- Josef Zipper Panthronics AG

## Track 13: Sensors, imagers and biomedical

- Angel Rodriguez-Vazquez CSIC
- Track Chair
- Andreas Demosthenous London's Global University Deputy Chair
- Ralf Brederlow Texas Instruments
- Werner Brockherde Frauenhofer IMS
- Eugenio Cantatore TU Eindhoven
- Antoine Dupret CEA
- Christian Enz EPEL
- Robert Henderson The University of Edinburgh
- Michael Mark Infineon
- Matteo Perenzoni FBK
- Albrecht Rothermel University of Ulm
- Chris (Jacques) Rudell University of Washington
- Hanspeter Schmid FH Nordwestschweiz
- Roland Thewes TU Berlin

## Track 14: Digital, security and memory

- Stefan Rusu TSMC
- Tobias Gemmeke imec

Track Chair

Deputy Chair

- Atila Alvandpour Linköping University
- Andreas Burg EPFL
- Sylvain Clerc STMicroelectronics
- Shidhartha Das ARM
- Tobias Noll RWTH Aachen
- Viktor Öwall Lunds University
- Praveen Raghavan imec
- Christoph Studer Cornell University
- Hannu Tenhunen KTH
- Ramses Valvekens Easics
- Ingrid Verbauwhede KU Leuven

## Track 15: Power management

- Michiel Steyaert KU Leuven
- Christoph Sandner Infineon
- Ke-Horng Chen NCTU Taiwan
- Johan Janssens ON Semiconductor
- Ravi Karadi NXP
- Lauri Koskinen University of Turku
- Yiannos Manoli University of Freiburg
- Bill Redman-White University of Southampton
- Drago Strle Uni Ljubljana
- Toru Tanzawa Shizuoka University
- Bernhard Wicht Leibniz University Hannover

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Track Chair Deputy Chair



#### WELCOME TO LEUVEN

With about 100.000 inhabitants, Leuven is well known as a university city. It is the home of the biggest university in Belgium, with more than 40.000 students. Founded in 1425 by Papal Bull under Martinus V, it is also the oldest university in Belgium.

The city of Leuven itself came in full bloom a few centuries earlier. Up to the end of the 13rd century, it was the residence of the Dukes of Brabant. Town and university have known many periods of prosperity. The town hall, churches, cloisters and colleges stand silent witness of those days and make Leuven an interesting place, rich in historical buildings that radiate a magic of their own. Major tourist attractions are the more than 550 year old town hall, the Great Beguinage, the University Library, the St. Peters Cathedral and the Papal college.

Triggered by the presence of imec, the largest independent research center in Europe with over 3500 researchers coming from more than 70 different countries, Leuven became a world leading center for micro and nano-electronics. KU Leuven and imec have created almost 200 spin-off companies. Leuven is also hosting the headquarters of AB INBEV, the largest brewery in the world.

Leuven is only 20 km away from Brussels, the capital of Belgium and hearth of Europe. It is ideally situated to visit world famous places like Antwerp, Gent and Bruges. Even the seaside or the Ardennes are less than 2 hours away.

The venue of the conference events, including workshops and tutorials, will be in the center of Leuven.

#### **GETTING AROUND LEUVEN**

### By Bus

The main local bus terminal is located next to the railway station (if you leave the station, it is on your right hand side). The busses easily reach Leuven centre and surrounding areas. Local busses are run by De Lijn (www.delijn.be)

## By Bike

You can hire bikes at a number of different locations in Leuven. (www.visitleuven.be/en/bike)

## By Taxi

Taxis can be found at the Leuven train station (in front of the main building) and at Smoldersplein (near the courthouse).

#### Taxi companies in Leuven:

- Taxi Alex
  - Bierbeekstraat 116, 3001 Leuven (Heverlee), Tel. +32 16 29 16 16
- <u>Taxi's Jenny NV</u>

Diestsesteenweg 489, 3010 Leuven (Kessel-Lo),

Tel. +32 16 25 35 65

- Taxi Gerard
  - Wipstraat 27, 3010 Leuven (Kessel-Lo),

Tel. +32 16 25 09 99

Cordons-Van Minsel BVBA

Hoveniersdreef 31, 3001 Leuven (Heverlee),

Tel. +32 16 22 20 00



#### KU LEUVEN CAMPUS OF SOCIAL SCIENCES

The ESSCIRC/ESSDERC Conference takes place in the city center of Leuven, at the:

## KU LEUVEN Campus of Social Sciences Parkstraat 45, 3000 Leuven, Belgium

#### HOW TO REACH THE VENUE

From the train station

By Foot

The Faculty of social Sciences is situated at walking distance (about 15 minutes) from the station. Follow 'Maria-theresiastraat' until it changes into 'Andreas Vesaliusstraat'. Then follow the 'Andreas Vesaliusstraat' up to the crossing with the 'Parkstraat'. Turn right here.

You will find the campus about 100m further at your right side.

By bus

Take the bus with number 4, 5 or 6 and alight at the stop called 'Remy' in the 'Andreas Vesaliusstraat'. Follow the 'Andreas Vesaliusstraat' until it crosses with the 'Parkstraat'. Then turn right. You will find the campus about 100m further at your right side.

#### **SESSIONS**

Sessions will be located in different buildings inside and just outside the Campus:

#### JOINT PLENARY SESSIONS

VESALIUS AULA (Andreas Vesaliusstraat, 3000 Leuven), just outside the Campus. The Andreas-Vesalius street is the continuation of the Maria-Theresiastreet and connects the campus directly to the train station.

## • ESSCIRC SESSIONS

Room AP 00.15 Auditorium Max Weber (AP) (Parkstraat 51, 3000 Leuven) inside the Campus Room **AV 91.12** Auditoria complex (**AV**) (Parkstraat 49, 3000 Leuven) inside the Campus Room AV 01.12 Auditoria complex (AV) (Parkstraat 49, 3000 Leuven) inside the Campus Room **AV 03.12** Auditoria complex (**AV**) (Parkstraat 49, 3000 Leuven) inside the Campus

#### ESSDERC SESSIONS

Room AP 01.30 Auditorium Jean Monnet (AP) (Parkstraat 51, 3000 Leuven), same building as Max Weber Auditorium but upstairs, inside the Campus Room AV 00.17 Auditoria complex (AV) (Parkstraat 49, 3000 Leuven) inside the Campus Room AV 02.17 Auditoria complex (AV) (Parkstraat 49, 3000 Leuven) inside the Campus

• TUTORIALS (Monday 11 September)

Room AV 01.12 Integrated Power Management in Research and Industry

Room AV 03.12 The Hidden Challenges of 5g

Room AV 00.17 Beyond Cmos

Room AV 02.17 Sensors for the lot Era Room AV 02.17 Neuromorphic Computing with Emerging Synaptic Devices

## • WORKSHOPS (Monday 11 September) Room AV 04.17 Connect

Room AV 91.12 Mos-AK Room AP 00.15 Sinano - Nereid

Room AP 01.30 Semiconductor Memories

#### • WOMEN IN CIRCUITS (Tuesday at 12:30 pm) At FlexiSpace inside KU Leuven Agorà Learning Centre (E. Van Evenstraat 4 - B-3000 Leuven) in the KU LEUVEN Campus of Social Sciences

• **ELECTRONIAD QUIZ** (Tuesday at 7:00 pm) Alma 2 - E. Van Evenstraat 2, Léuven

## REGISTRATION DESK

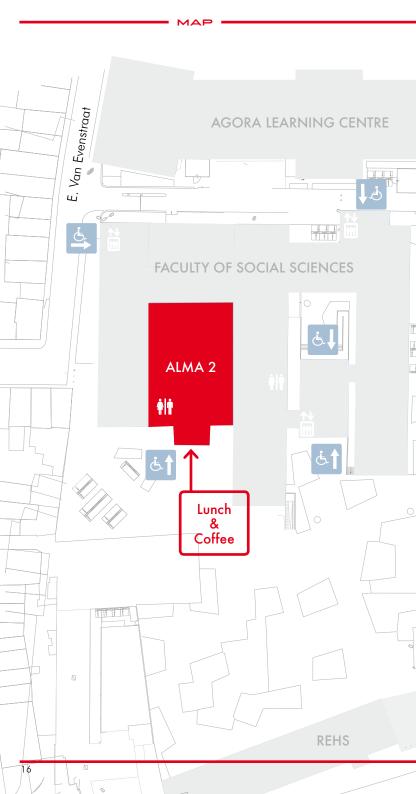
The Registration Desk will be located in the Max Weber/ Jean Monnet building (AP Auditoria).

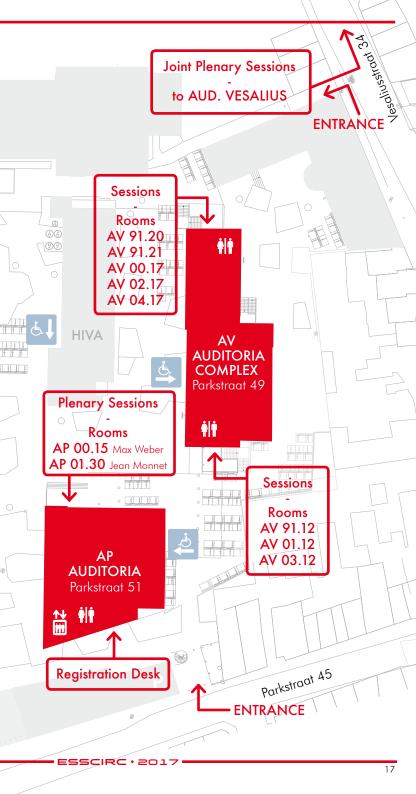
Registration Desk will move to VESALIUS AULA only

on Tuesday from 8.00 till 10.00 am.

#### COFFEE BREAKS AND LUNCHES

Breaks will be held in the Student Restaurant Alma 2 (Parkstraat 45, inside the Campus), which will be closed for the public during the conference.





		Morning Tutorials - Monday September 11th, 2017	mber 11th, 2017	
Time	AV01.12	AV03.12	AV00.17	AV02.17
	ESSCIRC	ESSCIRC Tutorials	ESSDERC Tutorials	<b>Futorials</b>
	Integrated Power Management in Research and Industry	The Hidden Challenges of 5G	Beyond CMOS	Sensors for the loT Era
08:00-08:30				Registrations
08:30-06:00	Registrations	Registrations	Registrations	Introduction and Overview Mirjana Banjevic
09:00-10:00	Integrated Switched-capacitor Power Converters: a Feasible Way to Get High Efficiency Power Conversion in Standard CMOS Technology Gerard Villar Piqué	What is Required of 5G to Make It Attractive for MTC? Yao-Hong Liu	Introduction to Beyond CMOS Iuliana P. Radu	Smart Sensors for Environmental Monitoring Florin Udrea
10:00-10:30		Coffee Break	Break	
10:30-11:30	Integrated Inductive and Hybrid DC- DC Converters Giovanni Frattini	Programmable mm-Wave Transmitters: Generalized PA Architectures for Frequency and Back- off Reconfigurability Kaushik Sengupta	Tunnel FETs – Status and Prospects Nadine Collaert	Sensors for Health Monitoring Patrick Mercier
11:30-12:30	Making Magnetics Disappear - Integrated Magnetics for Power Management Gan O'Mathuna	Implementing Massive MIMO Systems: Coarse Processing Gives Fine Performance Liesbet Van der Perre	Negative Capacitance FETs: Physics, Materials and Devices Asif Islam Khan	Sensors for Automotive Industry Appo van der Wiel
12:30-13:30		Lunch	ch	

		Arternoon ratorials - monday September 11111, 2011	CHIEGO THEIR POPE	
Time	AV01.12	AV03.12	AV00.17	AV02.17
	ESSCIRC	ESSCIRC Tutorials	ESSDERC	ESSDERC Tutorials
	Integrated Power Management in Research and Industry	The Hidden Challenges of 5G	Beyond CMOS	Neuromorphic Computing with Emerging Synaptic Devices
12:30-13:30				Lunch
13:30-14:00		Lunch		Neuro-inspired Computing using Resistive Synaptic Devices: Challenges and Prospects Shimeng Yu
14:00-15:00	Vibrational Harvesters for Wireless Sensing Applications Stefano Stanzione	Integrated Wide-band Baseband Filters and Narrow-band RF Filters for 5G Bram Nauta	Towards Functionality-Enhanced Devices: Controlling the Modes of Operations in Three-Independent-Gate Transistors Pierre-Emmanuel Gaillardon	Analog Synapse Devices based on Interface Resistive Switching for Neuromorphic Systems Hyunsang Hwang
15:00-15:30		Coffee	Coffee Break	
15:30-16:30	Power Management Design for Highly Integrated Automotive ICs Bernhard Wicht	Challenges in 5G Transmitter Design Christian Fager	Spintronics in the Context of Computation Titash Rakshit	Emerging Memories for Neurocomputing Dmitri Strukov
16:30-17:30	1 kV On-chip, Hard to Resist? Valentijn De Smedt	Opto Implementation Challenges for 5G Networks <i>Francesco Testa</i>	Introduction to Quantum Computing Ronald Hanson	Accelerating Backpropagation Training with Non-Volatile Memory: Devices, Circuits and Architecture Geoffrey Burr

	AP 01.30		08:30 - 11:15 SEMICONDUCTOR MEMORIES	Francisco Gamiz	Kilho Lee Manfrest Horstman	Elisa Vianello		Coffee 11:15 - 11:45		11:45 - 13:15	SEMICONDUCTOR MEMORIES (Continued)	Pierre Fazan Guohan Hu		Lunch 13:15 - 14:30	14:30 - 16:00 SEMICONDUCTOR MEMORIES (Continued) Philippe Galy Sorin Cristoloveanu Joris Lacord	Coffee 16:00 - 16:30	16:30 - 17: 45 SEMICONDUCTOR MEMORIES (Continued) Asen Asenov Andy Pickering
September 11, 2017	AP 00.15	08:00 Registrations	09:00 - 10:45 SINANO - NEREID Enrico Sangiorgi	Francis Balestra	Francisco Ibanez Jouni Abonelto	Clivia Sotomayor Torres	Coffee 10:45 - 11:00	11:00 - 12:45	SINANO - NEREID (Continued)	Anda Mocuta Yann Deval	Montserrat Fernandez-Bolanos	Steve Stoffels Stéphane Monfray	Lunch 12:45 - 14:00	14:00 - 16:00	SinANO - NEKELD (Continued) Danilo Demarchi Holger Schmid Georgios Fagas Thanasis Dimoulas Enrico Sangiorgi		
Workshops - Monday September 11, 2017	AV 91.12	08:00 Registrations	08:30 - 10:10 MOS-AK	Jim Greer	Marcelo Pavanello		Coffee 10:10 - 10:30		10:30 - 12:30	Mim Schoenmaker	Jean-Pierre Raskin	Chika Tanaka	Lunch 12:30 - 14:00		14:00 - 15:00 MOS-AK (Continued) Nicolas Cordero Ashkhen Yesayan	Coffee 15:00 - 15:30	15:30 - 17:00 MOS-AK (Continued) Denis Flandre Benjamin Iniguez Saravana Maruthamuthu
	AV 04.17	08:00 Registrations	08:30 - 10:10 CONNECT Aida Todri-Sanial	Salvatore M. Amoroso	Benjamin Uhlig Gaae Krieaer Hills	Esko Kauppinen	Coffee 10:10 - 10:40		10:40 - 12:30	CONNECT (Continued) Jean Dijon	Benjamin Uhlig	Marleen van der Veen	Lunch 12:30 - 14:00		14:00 - 15:10 CONNECT (Continued) Shu-Jen Han Bingan Chen	Coffee 15:10 - 15:40	15:40 - 17:00 CONNECT (Continued) Bernd Gotsmann Aida Todri-Sanial

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Time         AP00.15         AV31.12         AV0           08:00-08:30         Vesalius - Conference         Vesalius - A11-A:1           09:00-09:40         Vesalius - A11-A:1         F           10:20-11:00         A31-B         RF Receivers and Digital A0           12:20-14:00         A41-B         A41-C           A41-C         A41-C         A41-C	AV01.12 AV03.12 AP01.3  Vesalius – Registrations Inference Opening & Welcome (presentation by SSC sociative Engineering a Safe, Clean & Comfortable Future A2L-A: ESSDERC/ESSCIRC Joint Plenary 1: Françoise C RA1.4: ESSDERC/ESSCIRC Joint Plenary 2: Peter Real, Navigating without a Moore's Law Compass Coffee Break	Vesalius – Registrations  Welcome (presentation SSCIRC Joint Plenary 1:	L.12 AV0112 AV03.12 AP0130 AV00 Vesalius – Registrations Vesalius – Conference Opening & Welcome (presentation by SSC society and EDS society)	AV00.17	AV02.17
A31-B RF Recei References Detec Detections and A41-B A44 Amplifiers and Oscill	Verence Opening & V A1L-A: ESSDERC/ES: Engineering a A2L-A: ESSDERC/ES	salius – Registrations Velcome (presentation SCIRC Joint Plenary 1	s η by SSC society and E	DS society)	
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A31-B RF Receiver References Detectoo A41-B A41-C Amplifiers and Comparators Oscillatio	A1L-A: ESSDERC/ES: Engineering a A2L-A: ESSDERC/ES Navigating v	SCIRC Joint Plenary 1		(france)	
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A31-E References References Detectors A41-B A41-C Amplifiers and Comparators		SSDERC/ESSCIRC Joint Plenary 2: Peter Re Navigating without a Moore's Law Compass	Vesalius A2L-A: ESSDERC/ESSCIRC Joint Plenary 2: Peter Real, Analog Devices Navigating without a Moore's Law Compass	evices	
A31-B RF Receivers and Betectors Detectors A41-B AMURIFIERS and Comparators Oscillators		Coffee Break			
A4L-B A4L-C Amplifiers and Comparators	A3L-D Digital Accelerators	A3L-E Optical Sensors	A3L-F Resistive RAM	A3L-G Cross-Domain Compact Modelling	A3L-H Focus Session: Beyond CMOS Devices I
A4L-B A4L-C Amplifiers and Oscillators		Lunch			
20-15:50	A4L-D Wireline and Optical		A4L-F Alternative Device Simulations	A4L-G Parameter Extraction	A4L-H Focus Session: Beyond CMOS Devices II
		Coffee Break			
Room: AP00.15 A5L-B, ESSCIRC Keynote 1: Yves Baeyens: Solving Capacity Bottlenecks in Fixed Access Comms	leyens: cess Comms		A5L-F, ESSDERC Key Quantum Nano-Elect	Room: APO1.30 ASLF, ESSDERC Keynote 1: Ian Young: Principles and Trends in Quantum Nano-Electronics & Nano-Magnetics for Beyond-CMOS Computing	ciples and Trends in ics for Beyond-CMOS
46L-6 A6L-8 A6L-8 A6L-C	A6L-D Digital-intensive Frequency Synthesis	A6L-E Digital Processors		A6L-G Modelling of Emerging Devices	A6L-H 2D Material Devices
18:00-19:00 ESSCIRC TPC Mtg.			ESSDERC TPC Mtg.		
19:00-21:00 ESSDE	ESSDERC/ESSCIRC	ESSDERC/ESSCIRC 2017 Welcome Reception: Jubilee Hall	ption: Jubilee Hall		
Legend CIRC = CIRC Keynote =		DERC =	DERC Keynote =	ote =	Joint =

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			Wednes	Wednesday September 13th, 2017	h, 2017		
Time	AP00.15	AV91.12	AV01.12	AV03.12	AP01.30	AV00.17	AV02.17
08:30-08:45			Vesalius Prese	Vesalius Presentation on ESSCIRC/ESSDERC 2018	ESSDERC 2018		
08:45-09:25		Vesalius	- B1L-A: ESSDERC/ESS	/ESSCIRC Joint Plenary 3: Har Smart Power for Automotives	Vesalius – B1L-A: ESSDERC/ESSCIRC Joint Plenary 3: Hans Stork, ON Semiconductor Smart Power for Automotives	nductor	
09:25-10:10				Coffee Break			
10:10-12:10	B2L-B High Speed ADC	B2L-C Transmitters and Power Amplifiers for mm-Wave and IoT	B2L-D Biomedical Circuits and Systems		B2L-F Widebandgap Power Devices	B2L-G Advanced CMOS Characterization and Reliability	B2L-H Emerging Memory Technologies
12:10-13:30				Lunch			
13:30-14:10	B3L-B, ESSCIRC Keyn 5G Require	Room AP00.15 B3L-B, ESSCIRC Keynote 2: Sven Mattisson, Ericsson - Overview of 5G Requirements & Future Wireless Networks	ericsson - Overview of s Networks		B3L-F, ESSDERC K	Room AP0130 B3L-F, ESSDERC Keynote 2: Siva Sivaram - Storage Class Memories: Desire Meets Reality	n - Storage Class ality
14:20-15:40	B4L-B High Efficiency ADC	B4L-C 5G and mm-Wave Frequency Synthesis	B4L-D Machine Learning and Neuromorphic Computing	B4L-E Linear Regulators	B4L-F FinFEt and Nanowire Simulations	B4L-G Traps and Noise	B4L-H 2D Material Integration
15:40-16:00				Coffee Break			
18:00-23:00			Gala D	Gala Dinner: Autoworld (Brussels)	ssels)		
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#### LANGUAGE

The official language of the conference is English: no simultaneous translation will be available.

#### REGISTRATION DESK

The Registration Desk will be located in the Max Weber/Jean Monnet building (AP Auditoria) and it will be open the following hours throughout the Conference:

- Monday 11 September: 8.00 am 6.00 pm
- Tuesday 12 September: 8.00 am 5.00 pm
- Wednesday 13 September: 8.00 am 4.00 pm
- Thursday September: 9.00 am 4.00 pm

# Registration Desk will move to VESALIUS AULA only on Tuesday from 8.00 till 10.00 am.

#### **BADGES**

Badges must always be visibly worn during sessions, coffee breaks and lunches, and also during social program activities.

## **COFFEE BREAKS AND LUNCHES**

Coffee breaks and lunches will be served to registered participants wearing their badges. Accompanying persons have no access to scientific sessions nor to coffee breaks and lunches. Please note that vegetarian dishes will be on daily menu; for other special needs, we will try to serve a good variety of food so that it will be easier for you to get some alternatives in case of special diet restrictions.

#### PERSONS WITH SPECIAL NEEDS

Every effort has been made to ensure that people with special needs are catered for during the conference. Should you require any specific assistance, please let us know in advance to enable to assist in making your stay at the conference a pleasant and comfortable one.

## INTERNET / WI-FI

Wi-Fi connection will be available on site.

#### CERTIFICATE OF ATTENDANCE

Certificates will be sent by email upon request to essxxrc@sistemacongressi.com, after the Conference.

#### LIABILITY

In registering for the conference, participants agree that neither the Scientific/Organizing Committees nor the Organizing Secretariat assumes any liability.

#### **CURRENCY**

The local currency is € (Euro). Automatic teller machines and exchange offices are available in Leuven city centre. Most hotels, restaurants and shops accept major credit cards but please always check first!

#### **ELECTRICITY**

Electricity is 220-230V, 50 Hz. Belgian plugs have two round pins.

## CALLING CODES

Belgium country code: +32 (or 00 32)

Leuven: +32 (0)16

## **EMERGENCY NUMBERS**

European emergency number: 112

## PHARMACY APOPARK

Address: Tiensestraat 81, 3000 Leuven

Phone: 016/22.20.48 Website

Opening hours: Mo - Fr: 8.30 am - 18.00 pm, Sa 8.30 am to noon

## STORE OPENING HOURS

Most shops are open from Monday till Saturday, 10:00 am - 18:00 pm

#### **SMOKING**

No smoking in public places (e.g. airports, train stations, schools, universities, restaurants, bars and cafes, government buildings) and on public transport.



# WELCOME COCKTAIL AT JUBILEE HALL Tuesday 12 September

From 7 pm until 9 pm

It is located in the University Hall, the university's main building in the city centre.

## University Hall, Naamsestraat 22, Leuven

This prestigious building of 1317 was originally the municipal Cloth Hall and only comprised a ground floor in Gothic style. In 1432 the newly founded university was housed in the wing on the Krakenstraat. The hall was used as a lecture hall until the First World War. In 1679 the city sold the entire building to the University that immediately built the baroque first floor. In 1723 the Rega wing was added (classical sandstone façade overlooking Oude Markt).

#### Rate

Free for conference participant Additional Welcome Cocktail ticket: € 30,00



## GALA DINNER AT AUTOWORLD Wednesday 13 September From 6 pm until 11.30 pm

## Jubelpark 11, 1000 Brussels

The museum's housing treasures of the history of the motor car, thanks to Ghislain Mahy's and his family's gamble, and the gentle but uncontested force of persuasion of a prince who later became King Albert II. They were helped by the combined support of the ministerial responsibilities of the late vice-president of Autoworld, Minister Louis Olivier, formerly in charge of public works, and President Herman De Croo, communications minister for eight years. Autoworld is a highly-colorful environment adapted for teaching purposes and created to continue evolving on a non-stop basis.

Decades of evolution in technology, comfort, safety and increasing concern with the environment are on display here via superb coaches and countless motorized vehicles. From the earliest models of the distant past to contemporary cars that prefigure the automobile of tomorrow and beyond, the visitor is guided through the fabulous history of the motor car thanks to technical but easily comprehensible commentaries.

#### Rate

Free for conference participant Additional Gala Dinner ticket: € 150.00

## How to get

Buses will be provided from Leuven to Autoworld and back (no intermediate stops will be possible). Information will be available at the registration desk.

The aim of ESSDERC and ESSCIRC is to provide an annual European forum for the presentation and discussion of recent advances in solid-state devices and circuits. The increasing level of integration for system-on-chip design made available by advances in semiconductor technology is, more than ever before, calling for a deeper interaction among technologists, device experts, IC designers and system designers. While keeping separate Technical Program Committees, ESSDERC and ESSCIRC are governed by a common Steering Committee and share Plenary Keynote Presentations and Joint Sessions bridging both communities. Attendees registered for either conference are encouraged to attend any of the scheduled parallel sessions, regardless to which conference they belong.

## **ESSCIRC 2017 Tracks**

- Analog
- Data Converters
- RF and mm-Wave
- Frequency Generation
- Wireless and Wireline Systems
- Sensors, Imager and Biomedical
- Digital, Security and Memory
- Power Management

## **ESSCIRC/ESSDERC Focus Tracks**

- Neuromorphic Computing
- Quantum Computing

## FRANÇOISE CHOMBAR CEO Melexis, Belgium

## Engineering a safe, clean and comfortable future



Ms. Françoise Chombar has been the Chief Executive Officer of Melexis NV, since 2004 and has been its Managing Director since February 15, 2011. Ms. Chombar serves as the Chief Executive Officer of Melexis Microelectronic Integrated Systems N.V. She is the Co-Founder of Melexis. Ms. Chombar served as Chief Operating Officer of Melexis NV since 1994. She served as Chief Executive Officer for Operations, Sales and Human Resources of Epig Nv since 2004 and its Acting Chief Operating Officer since 1994. She served as Planning Manager at Elmos GmbH, a German semiconductor company, from 1986 to 1989 and as Commercial Assistant at Michel Vande Wiele n.v., a Belgian textile equipment manufacturer, from 1984 to 1985. Since 1989 she served as a Operations Manager of Elex-Xtrion group since 1989. Ms. Chombar has been a Director of Epig NV since 1996 and Melexis NV since 1996. She has been an Independent Non-Executive Director of Umicore S.A. since April 26, 2016. She served as an Independent Director of EVS Broadcast Equipment S.A. since May 2012. She served as a Director of Elex-Xtrion group. She's been mentor of the Women's network Sofia since 2000, a member of Women on Board since 2011 and honorary ambassador of the Department of Applied Languages of the University of Gent since January 2012.

Ms. Chombar holds a Master Degree as Interpreter in Dutch, English and Spanish from the University of Gent.

## TETSUO ENDOH Professor Tohoku University, Japan

## Spintronics applications: STT-MRAM and Non Volatile Logic



Tetsuo Endoh joined ULSI Research Center Toshiba Co. in 1987 and was engaged in the R&D of NAND Memory. He became a lecturer at the Research Institute of Electrical Communication, Tohoku University in 1995. He is a professor at the Department of Electrical Engineering, the Graduate School of Engineering, Tohoku University and director of the Center for Innovative Integrated Electronic Systems (CIES). His current interests are novel 3D structured device technology, such as Vertical MOSFETs; high-density memory, such as SRAM, DRAM, 3D-NAND memory and STT-MRAM; and beyond-CMOS technology, such as spintronics-based non-volatile Logic for ultralow power systems such as mobile systems, Al systems and IoT systems.

He is also interested in power-management technology, such as GaN on Si based power devices and power integrated circuits with low energy loss and low power consumption for automotive applications. He received the 14th Prime Minister's Award for its Contribution to Industry-Academia-Government Collaboration in 2016. He received 2017 National Invention Award "the 21st century Encouragement of Invention Prize" on June 12th.

# PETER REAL Senior VP & CTO Analog Devices Inc.

## Navigating without a Moore's Law Compass



Peter Real is Senior Vice President and Chief Technology Officer of Analog Devices. In this role, Mr. Real works closely with ADI's business units and manufacturing operations to provide a long term technology and capability vision for the company which drives ADI's competitive advantage. He is responsible for the identification, sourcing, and nurturing of new business, technology, and research opportunities while also being responsible for the development of foundation capabilities in support of current and future needs. Previously, Mr. Real held the positions of Vice President of the High Speed Products and Technology Group, Vice President of the Linear and Radio Frequency Products and Technology Group, Vice President of the Radio Frequency and Networking Products Group, and various design engineering and product line leadership roles.

Mr. Real holds Bachelor of Science and Master of Science degrees in Electrical Engineering, and is the author or co-author of nine patents.

# HANS STORK Senior VP & CTO ON Semiconductor, USA

#### **Smart Power for Automotives**



Dr. Hans Stork is Senior Vice President and Chief Technology Officer (CTO) at ON Semiconductor. He oversees the development of wafer process technologies, modeling and design kits, design libraries, as well as packaging technologies and assembly support.

Prior to joining ON Semiconductor, Dr. Stork was Group Vice President and CTO of the Silicon Systems Group at Applied Materials. From 2001 to 2007 he was Senior Vice President and the CTO of Texas Instruments. Before that, Dr. Stork held various R&D and management positions at Hewlett Packard Laboratories and at IBM's T.J. Watson Research Center.

Dr. Stork serves on the supervisory board of ASML, is a member of the Scientific Advisory board at imec, and has previously served on the boards of Sematech and the SRC. He is also a longstanding member of the SIA Technology Strategy Committee. He authored more than 100 cited papers and holds 11 U.S. patents. He was elected IEEE Fellow in 1994, and served on several IEEE sponsored conference program committees, and is currently vice-chair of the Technical Field Awards Council and a member of the Awards Policy and Portfolio Review Committee.

Dr. Stork was born in Soest, The Netherlands, and received the Ingenieur degree in electrical engineering (EE) from Delft University of Technology, Delft, The Netherlands, and holds a PhD in EE from Stanford University.

## ESSCIRC ELENARY KEYNOTES

### YVES BAEYENS Nokia Bell labs, Belgium

## Solving Capacity Bottlenecks in Fixed Access Comms



Yves Baeyens received the PhD degree in Electrical Engineering from the KU Leuven, Belgium in 1997. After his PhD, he spent one and a half year as a visiting scientist at the Fraunhofer Institute for Applied Solid-Sate Physics in Freiburg, Germany.

Since 1998, he has been with Bell Laboratories, currently the research division of Alcatel-Lucent. He is now Director of the High-Speed Electronics and Opto-Electronics Research Department in Murray Hill, NJ. His main research interests are the architecture, the design and technology of electronics and opto-electronic circuits for terabit optical and multi-gigabit wireless applications.

Yves Baeyens is a Fellow of IEEE and was nominated and selected for the National Academy of Engineering 2009 US and 2011 US/EU Frontiers in Engineering Symposia. He authored or coauthored over 100 publications on high-speed semiconductor technologies and circuits.

Since 2003, Yves Baeyens is an adjunct professor at the Department of Electrical Engineering of Columbia University, New York City, NY, where he teaches a graduate course on advance microwave circuit design.

## ESSCIRC PLENARY KEYNOTES

## HARISH KRISHNASWAMY

Professor Columbia University, USA

Integrated Antenna-Interface Components – A Blessing for Wireless Transceivers



Harish Krishnaswamy received the B.Tech. degree in Electrical Engineering from the Indian Institute of Technology-Madras, India, in 2001, and the M.S. and Ph.D. degrees in Electrical Engineering from the University of Southern California (USC) in 2003 and 2009, respectively. He joined the EE department of Columbia University as an Assistant Professor in 2009.

He received the IEEE International Solid State Circuits Conference (ISSCC) Lewis Winner Award for Outstanding Paper in 2007. He also received the Best Thesis in Experimental Research Award from the USC Viterbi School of Engineering in 2009, and the DARPA Young Faculty Award in 2011.

### ESSCIRC ELENARY KEYNOTES

### **SVEN MATTISSON**

Corp. Senior Expert Ericsson, Sweden

### Overview of 5G requirements and future wireless networks



Sven Mattisson received his PhD in Applied Micro Electronics from Lund University in 1986. From 1987 through 1994 he was an associate professor in Applied Micro Electronics in Lund where his research was focused on circuit simulation and analog ASIC design. In 1995 he joined Ericsson in Lund to work on cellular handset development.

Presently he is with Ericsson Research in Lund, where he holds a position as senior expert in analog system design. Since 1996 he is also an adjunct professor at Lund University. Dr. Mattisson is a coinventor of Bluetooth and has been serving as technical program committee member for the International Solid-State Circuits Conference and the European Solid-State Circuits Conference. Presently he is working on 5G radio circuits

All tutorials will be held on Monday 11 September. 08.00 - 09.00 Registrations

# INTEGRATED POWER MANAGEMENT IN RESEARCH AND INDUSTRY

Tutorial Organizer: Gerard Villar Piqué, NXP Semiconductors

Room AV 01.12

### GERARD VILLAR PIQUÉ

09.00 - 10.00

Integrated switched-capacitor power converters: a feasible way to get high efficiency power conversion in standard CMOS technology

### Abstract

Since they do not require inductors, switched-capacitor power converters (SCPC) have become a feasible way to implement more efficient power converters/voltage regulators fully integrated in standard CMOS technologies. This has increased the interest for them in both industry and academia. However, their performance is strongly impacted by the non-idealities of the integrated components, making their design challenging. Also, providing an efficient voltage regulation for a wide range of input voltage is not straightforward. This tutorial will cover the most relevant design aspects, including different tricks to overcome the main sources of energy loss, different implementations for the floating capacitors, the most popular control methods and topologies comparison. Different examples from industry and academy will be provided.

### Bio

Gerard Villar Piqué received the M.Sc. degree in 2001, and the Ph.D. degree in 2007 from the Technical University of Catalonia, Barcelona. In April 2008, he joined the Mixed-Signal Circuits and Systems Group, at the Research Department of NXP Semiconductors, Eindhoven (The Netherlands). As Principal Scientist of the Power Management team at AMSIP, he is involved in research on integrated power management systems. His main research areas include mixed-signal and analog microelectronics design, as well as power management systems (including switched-mode power supplies), with special focus in low-power fully-integrated switched-capacitor DC-DC converters. He has published a book on monolithic integration of inductive switching power converters. He is a member of the Technical Program Committee of ESSCIRC, ISSCC and PowerSoC.

# 10.00 - 10.30

### GIOVANNI FRATTINI 10.30 - 11.30

### Integrated inductive and hybrid DC-DC converters

### Abstract

Starting from the basic principles of switching power converters, this tutorial will discuss the techniques associated with design of these kind of devices as integrated circuits and present approaches such as hybrid inductive-capacitive converter topologies which can enable further integration at the cost of increased complexity. The associated tradeoffs will be discussed.

### Bio

Giovanni Frattini received his MS degree in electronic engineering from U. of Pavia in 1997. The same year he joined STMicroelectronics in Milan, Italy, as an Analog Designer in the BCD technology R&D, where he worked on designing signal analog circuitry for smart power chips, data converters, HV linear and DC/DC power converters. Joined National Semiconductor (now Texas Instruments) in 2008 to start and lead the R&D team in the Design Center located in Milan, Italy, currently responsible for the R&D teams in Italy and Germany for power management applications.

His current research interests include fully integrated power converters, high voltage applications, high frequency switching power conversion, isolated power converters.

### CIAN O'MATHUNA 11 30 - 12 30

# Making Magnetics Disappear Integrated Magnetics for Power Management

### Abstract

The work-horse of power management, the dc-dc switched-mode converter, can deliver high-efficiency power to multi-voltage rails in electronic loads such as microprocessors and to multiple peripherals in portable electronics such as screens, cameras and audio units. One of the major drawbacks of existing dc-dc converter technology is the need for off-chip capacitors and bulky inductors for energy storage and filtering. These passive components take up significant space, and profile, on the electronics motherboard, add to the cost of the bill of materials and can impact on the overall system performance.

Moving to very high frequency (in the 20 to 200MHz range) magnetic inductors and transformers for dc-dc converters allows the inductance values to be reduced enabling dramatic miniatursation of the magnetics and the overall converter footprint and profile. This miniaturisation can be enabled by thin film 'magnetics-on-silicon' technology.

This tutorial will discuss the trends in moving to miniaturised power converter platforms. The tutorial will introduce 'magnetics on silicon' and will cover design, thin-film magnetic materials and MEMS fabrication of micro-inductor and micro-transformer components. Fabricated devices will be presented along with the performance of the components in real converters. Finally, a perspective on the future opportunities and challenges will be discussed

### Bio

Prof. Ó Mathúna is Head of Strategic Programmes at Tyndall National Institute, University College Cork, Ireland. His research is focused on making and powering the smart things for the Internet of Everything. He is co-author of more than 200 publications and has 30+ years in research/technology transfer to global electronics companies. In 2005, he was co-founder of the industry/academic group, PEIG (Power Electronics Ireland Group). He has been a Director of the PSMA (US-based Power Sources Manufacturers Association) and co-chair of its Packaging Committee. In 2008, he founded the International Workshop on Power Supply-on-Chip (PwrSoC), the global flagship for PSMA and the IEEE Power Electronics Society. In 2013, he was named IEEE Fellow in the field of power electronics "for leadership in the development of power supply using micromagnetics on silicon".

# **LUNCH** 12.30 - 14.00

### STEFANO STANZIONE

14.00 - 15.00

### Vibrational harvesters for wireless sensing applications

### Abstract

Wireless sensing is a promising technique for sensing the state of moving parts in industrial and automotive applications, allowing improvements of safety and reliability. Unfortunately, the best place for sensing is often not the best for wiring power cables. Batteries can solve the energy problem, but their periodic recharge or replacement is expensive. This makes energy harvesting from mechanical vibrations a very promising solution. However, multiple challenges will need to be solved to make these solutions practical. A successful product should combine low-power sensor and power management designs and efficient harvester interface. Additionally, the system will need to be effective despite the variations in time of available power.

#### Bio

Stefano Stanzione received the M.S. degree in electrical engineering and the Ph.D. degree from the University of Pisa, Pisa, Italy, in 2006 and 2010, respectively. His Ph.D. work focused on the analog building blocks of autonomous UHF RFID tags. He joined the Holst Centre/imec, Eindhoven, The Netherlands, in 2010, where he is currently an Analog Design Engineer. His current research interests include ultralow-power circuits for energy harvesting and battery management. Dr. Stanzione has been a member of the Analog Technical Program Sub-Committee of ISSCC since 2014

15 00 - 15 30

SSCIRC • 2017

### BERNHARD WICHT

15.30 - 16.30

# Power Management Design for Highly Integrated Automotive ICs

### Abstract

With the adoption of more electronics, vehicles become safer, cleaner, more comfortable, and more affordable and will soon support autonomous driving. Overall system size and cost require highly integrated power management solutions. With the introduction of the 48V board net in addition to the conventional 12V battery, there is an increasing need for point-of-load converters that can handle high input voltages. The high-voltage electrical drive train (400V) demands for galvanic isolated and highly integrated gate drivers for signal and power transfer. This talk gives a general introduction into circuit and system design for high-Vin DCDC converters and gate drivers for automotive applications. A particular focus will be on concepts and trends towards higher integration. This includes fast switching, which scales down the size of passive components. Moreover, digital control loops eliminate external passive components and provide flexibility as well as performance advantages over conventional analog control. The concept of high-voltage charge and energy storing enables area-efficient gate driver designs with a minimum of external components.

#### Rio

Bernhard Wicht received the Dipl.-Ing. degree in electrical engineering from University of Technology Dresden, Germany, in 1996 and the Ph.D. degree from University of Technology Munich, Germany, in 2002. Between 2003 and 2010, he was with the Mixed-Signal Automotive business unit of Texas Instruments in Freising, Germany, responsible for the design of automotive ICs for power management, motor control and transceivers. Between 2010 and March 2017, he was a full professor for integrated circuit design and a member of the Robert Bosch Center for Power Electronics at Reutlingen University, Germany. In April 2017, he become the head of the Mixed-Signal IC Design group at Leibniz University Hannover, Germany. His research interest includes power management and gate driver IC design.

### VALENTIJN DE SMEDT 16.30 - 17.30

### 1 kV on-chip, hard to resist?

### Abstract

This tutorial focuses on the design issues of ultra high voltage (up to 1000 V), high-power integrated circuit design. The speaker will discuss the complete design flow of a high voltage design case. In the first part, some technological aspects are discussed, such as parasitic coupling, shielding, oxide trenches, etc. Afterwards, several circuit solutions to cope with high-voltage transients are presented and discussed into detail. Special attention will go to simulation issues in high-voltage design. The next step in the design process is layout; as can be expected, several specific DRC rules need to be taken into account to obtain a working design, without the risk of early breakdown. DRC tools are a great help to obtain a working layout, however, they are only as smart as the person who implemented or uses them. Finally, also issues as packaging, heat dissipation and testing will be discussed. It is clear that special packaging techniques are required to handle these high voltages and high power dissipation, not to mention the increased risk for the test engineer.

### Bio

Valentijn De Smedt (S'08) was born in Lubbeek, Belgium, in 1984. He received the M.Sc. degree in electrical engineering from the Katholieke Universiteit Leuven in 2007. From 2007 to 2014 he was working as a research assistant at the MICAS laboratories of the Katholieke Universiteit Leuven towards a PhD degree on the design of ultra-low-power time-based building blocks for wireless sensor networks, which he received in April 2014. Since 2014 he is employed at MinDCet as a Senior Design Engineer. At MinDCet his focus in on the development of high-voltage (> 500V), high-power (>1kW) radiation hardened motor drivers and power converters. Since September 2016 he is part-time post-doctoral researcher at the KU Leuven technology campus in Geel.

All tutorials will be held on Monday 11 September. 08.00 - 09.00 Registrations

### - THE HIDDEN CHALLENGES OF 5G -

Tutorial Organizer: Fredrik Tillman, Ericsson Research Room AV 03.12

**YAO-HONG LIU** 09.00 - 10.00

### What is required of 5G to make it attractive for MTC?

### **Abstract**

In this tutorial, several IoT wireless standards for machine type communication (MTC) will be reviewed. The baseline 5G radio performance that is needed to compete with these IoT standards will be discussed, including an analysis of the battery energy consumption of an MTC device. Finally, the design challenge of the RF transceiver for 5G MTC, such as CMOS PA integration, will be addressed with few subGHz IoT transceivers as case study.

### Bio

Yao-Hong Liu (S'04-M'09) received his Ph.D. degree from National Taiwan University, Taiwan, in 2009.

He joined Terax Communication, VIA technology, and mobile devices, Taiwan, from 2002 to 2010. Since 2010, he joined imec, the Netherlands. His current research focuses on the ultra-low power and highly digitally-assisted RF transceivers for wireless healthcare and Internet-of-Things (IoTs) applications. He currently serves as a technical program committee of the

He currently serves as a technical program committee of the IEEE RFIC symposium.

**COFFEE BREAK** 10.00 - 10.30

### KAUSHIK SENGUPTA

10.30 - 11.30

# Programmable mm-Wave Transmitters: Generalized PA Architectures for Frequency and Back-off Reconfigurability

### **Abstract**

The evolution of 5G and future standards are expected to open up several disjointed frequency bands in the mm-Wave frequency range, giving us access to a spectrum with a collective span that is orders of magnitude larger than we had at any point in our history. Future wireless communication architectures need to be designed to allow optimally efficient use of these available spectral resources. Evidently to serve across the disjointed bands spreading across 70-100 GHz in future, deploying large-scale MIMO arrays with dedicated, multiple, narrow-band Tx-Rx architectures becomes inefficient and non-scalable. In this talk, we will present our approaches towards a transmitter and power amplifier architecture that can be reconfigured to operate near optimally over a large chunk of the mm-Wave spectrum. Frequency-reconfigurable integrated mm-Wave transmitters with high power and high back-off efficiency is a hard problem. In this talk, we will present a systematic methodology that allows impedances to be synthesized dynamically for both frequency and back-off reconfigurability by exploiting interactions of multiple digital PA cells in a general multi-port network. With the ultimate aim of an universal front-end, we present a systematic methodology for synthesis of this reconfigurable architecture that loosens the classical trade-offs between output power, efficiency, spectral efficiency (linearity) and spectral reconfigurability.

### Bio

Dr. Kaushik Sengupta received the B.Tech. and M.Tech. degrees in electronics and electrical communication engineering from the Indian Institute of Technology (IIT), Kharagpur, India, both in 2007, and the M.S. and Ph.D. degrees in electrical engineering from the California Institute of Technology, Pasadena, CA, USA, in 2008 and 2012, respectively. In 2013, he joined the faculty of the Department of Electrical Engineering, Princeton University, Princeton, NJ, USA.

He received the Young Investigator Program Award from Office of Naval Research in 2017 and two time inductee into `Princeton Engineering Commendation List for Outstanding Teaching'. He was the recipient of the Charles Wilts Prize in 2013 from Caltech for the best Ph.D. thesis in Electrical Engineering in 2012, the Caltech Institute Fellowship and the Prime Minister Gold Medal Award of IIT (2007). He serves on the Technical Program Committee of IEEE Custom Integrated Circuits conference and European Solid-state Circuits Conference. He was the recipient of the IBM Ph.D. fellowship (2011), the IEEE Solid-State Circuits Society Pre-doctoral Achievement Award (2012), the IEEE Microwave Theory and Techniques Graduate Fellowship (2012), and the Analog Devices Outstanding Student Designer Award (2011). He was the co-recipient of the IEEE RFIC Symposium Best Student Paper Award in 2012 and 2015 Microwave Prize from IEEE Microwave Theory and Techniques Society for the most influential paper in the field of interest to IEEE MTT-S society in 2013.

### LIESBET VAN DER PERRE 11.30 - 12.30

# Implementing Massive MIMO systems: coarse processing gives fine performance

### Abstract

Massive MIMO opens up a new dimension of wireless communications by using an excess of base-station antennas, relative to the number of active terminals. The technique has been demonstrated to achieve a record spectral efficiency through very efficient spatial multiplexing, attainable using linear processing in a time-division duplex mode. The concept through the excess of antennas can also realize radical improvements in energy efficiency, making it a key candidate technology for 5G wireless systems.

Essential to achieve the gains in practise, is the ability to realize the many antenna paths at low complexity. In this lecture we will zoom in on the implementation of Massive MIMO systems, and demonstrate that coarse processing can give fine performance. Specific aspects that will be handled include:

- Introduction to the Massive MIMO concepts.
- Power consumption and complexity breakdown of Massive MIMO systems.
- Exploiting system concepts for low complexity processing.
- Analog processing requirements: relaxing PA and convertor designs and power consumption.
- Efficient DSP for many antenna paths: Algorithm-architecture-circuit co-design.
- A perspective on lean terminals.

An overall status of Massive MIMO technology will be provided. The main challenges to be resolved in order to pave the way for actual deployment will be highlighted.

### Bio

Liesbet Van der Perre received the M.Sc. and PhD degree in Electrical Engineering from the KU Leuven, Belgium, in 1992 and 1997 respectively. She was appointed honorary doctor at Lund University, Sweden, in 2015. She joined imec's wireless group in 1997 and took up responsibilities as senior researcher, system architect, project leader and program director, until 2015. She was appointed Professor at the Electrical Engineering Department of KU Leuven in 2016. Liesbet is a (co-)author of over 300 scientific publications. She is the scientific leader for the FP7-MAMMOET project. Prof. Van der Perre is member of the Board of Directors of Zenitel and guest Professor at the University of Lund.

# **LUNCH** 12.30 - 14.00

# **BRAM NAUTA** 14.00 - 15.00

### Integrated wide-band baseband filters and narrow-band RF filters for 5G

### Abstract

Future 5G communications will operate at mm wave RF frequencies where wide band channels are available. This implies that the "baseband" filters for channel selection and anti-aliasing will have bandwidths in the order of a GHz. Given the fact that the building blocks of those filters need to be a factor 100 faster, this places serious design challenges on these circuits.

Also on the RF receiver side, there is a desire to have narrow band selectivity in order to remain interferer robust. Recently, N-path filters and mixer-first receivers have demonstrated that frequency translated filtering can combine a high linearity with low noise and frequency tuneability over a wide range of RF frequencies.

This tutorial will cover the basics of analog filters: synthesis, fundamental trade-offs in power dissipation, SNR, Q, and operating frequency. Also for frequency translated narrow band RF filters the basics and fundamentals are explained. The tutorial will be illustrated with several implementation examples.

### Bio

Bram Nauta received the M.Sc. and Ph.D. degrees from the University of Twente, Enschede, The Netherlands in 19:87 and 1991 respectively. After that he joined Philips Research laboratories in Eindhoven the Netherlands. In 1998, he returned to the University of Twente, where he is currently a distinguished professor, heading the IC Design group and chair of the EE department. He served as the Editor-in-Chief (2007-2010) of the IEEE Journal of Solid-State Circuits (JSSC), and was the 2013 program chair of the International Solid State Circuits Conference (ISSCC). He is IEEE fellow and currently the president elect of the IEEE Solid-State Circuits Society.

# **COFFEE BREAK** 15.00 - 15.30

### CHRISTIAN FAGER 15.30 - 16.30

### Challenges in 5G transmitter design

### Abstract

This talk will give an overview to some of the new challenges that will drive the development of transmitters in 5G systems and beyond. Massive multi-antenna transmitter architectures and millimeter wave frequencies will be key technology ingredients to facilitate the dramatic improvements in capacity, energy efficiency and reliability needed.

As we will discuss in this talk, this paradigm shift will force us to revisit the fundamental linearity and efficiency tradeoffs that typically dictate the design of transmitters in general and power amplifiers in particular. Focusing on millimeter wave silicon CMOS and BiCMOS transmitter circuit realizations, promising power amplifier circuit and transmitter architectures will therefore be reviewed in the context of 5G requirements.

Further challenges arise when these transmitter circuits are implemented as part of a low-cost highly integrated multi-antenna package. We will present a new system simulation framework that enables an accurate prediction of the joint nonlinear effects of circuit-, antenna- , and thermal design. Different phased array and massive MIMO transmitter examples will illustrate typical applications and the importance of codesign in highly integrated 5G transmitters.

#### Bio

Prof. Christian Fager received his M.Sc. and Ph.D. degrees from Chalmers University of Technology, Sweden, in 1998 and 2003, respectively. Since 2015 he is a Professor at the Microwave Electronics Laboratory at the same university. Dr. Fager has authored and co-authored more than 100 papers in international journals and conferences. His research focuses on design, characterization and modelling of energy efficient and linear transmitter circuits for future wireless communication and sensor systems. Dr. Fager is currently an Associate Editor of IEEE Microwave Magazine.

# **FRANCESCO TESTA** 16.30 - 17.30

### Opto implementation challenges for 5G networks

### Abstract

Silicon Photonics is recognized to be the technology best suitable to develop high scale integration optical system on chip.

The exploitation of the same highly developed CMOS manufacturing infrastructure and material used for electronic integrated circuits should ensures low cost and mass-manufacturability. The energy-efficient physical mechanisms used to process high capacity optical data flows, the small dimensions of the photonic circuits made possible by the high refractive index contrast of silicon photonics and the tight integration of photonic with the control electronic, allowed by the use of the same production technologies, should ensure low power consumption.

The characteristics of this technology, the strengths and weakness are discussed. The status of development for both commercial devices and experimental prototypes are reported. The challenges to be overcome in the near future, for the exploitation of the full potential of this technology and for extending the range of application of photonics, are also discussed.

The recent advancements achieved in the realization of high scale photonic integrated circuits could drive the introduction of optical switching and networking in new application areas where these functions could be advantageously exploited but this is prevented by the cost and footprint of conventional optical technologies based on discrete components. New optical system for radio access and data centers applications will be presented and discussed together with the enabling silicon photonics integrated devices. Finally, future perspectives and research directions are given.

#### Bio

Francesco Testa is a Principal Researcher at Ericsson Research in Pisa, Italy, focusing on photonics integrated technologies and their system applications. He started working in 1985 at Alcatel FACE Research Center in Rome, investigating coherent optical networks and related technologies. He joined Ericsson in 1991 to work on the first demonstrations of WDM optical transport systems, and later in optical networks architectures and technologies research, followed by several years spent on design of HW circuits and systems for SDH, ATM, LMDS, GSM, DECT and Narrowband Access. Francesco received his degree in Electronic Engineering, summa cum laude, from the University of Rome.

### CONNECT Room AV 04.17

### **Abstract**

The workshop will provide technical information about emerging interconnect technologies, with the focus on Carbon Nanotubes (CNT). A broad overview of all the major aspects of CNT interconnects will be offered, ranging from the innovative growth/deposition techniques of local and global lines to the novel measurement and simulation methodologies developed to characterize CNT performances. The core of the workshop will be based on the latest results arising from the research within the H2020 EU-funded project CONNECT. Invited talks from academia, research centers and industry will enrich the global perspective of the workshop.

### Target Audience

The target audience is students, researchers, engineers and entrepreneurs who have an interest or work in the areas related to advanced and future interconnects for integrated circuits. Since interconnects delay is a major limitation to circuits performance, anyone interested in advanced CMOS technologies will benefit from the topics addressed by the workshops' talks. Researchers working in the field of Carbon Nanotubes, even if not for with direct application in interconnects technology, will also find cross-disciplinary interest in this workshop. Finally, CMOS circuit designers will be able to gather useful information on modeling, design and optimization opportunities offered by Carbon Nanotubes based technologies.

# Background on CONNECT Project CarbON Nanotube compositE InterconneCTs

As the chip size goes down, interconnects become major bottlenecks irrespective of the application domain due to electromigration issues and an ever-increasing power consumption. The CONNECT project investigates ultra-fine CNT lines and metal- CNT composite material for addressing the issues of current state-of-the-art copper interconnects. Novel CNT interconnect architectures for the exploration of circuitand architecture-level performance and energy efficiency will be developed. CMOS compatibility as well as challenges of transferring new processes into industrial mass production will be addressed. The members of the CONNECT consortium from Germany, Switzerland, Great Britain and France are embedded along the electronics value chain from fundamental research to end-users and bring together some of the most renowned research groups in that field in Europe. With significantly improved

electrical resistivity, ampacity, thermal and electromigration properties of CNT interconnects compared to state-of-the-art approaches for conventional copper interconnects, an increased power and scaling density of CMOS or CMOS extension will be available and applicable to alternative computing schemes such as neuromorphic computing. The technologies developed in this project are key for both performance and manufacturability of scaled microelectronics to manifest miniaturized microelectronic products with enhanced functionality at ever decreasing cost. The procurement of CONNECT will foster the recovery of market shares of the European electronic sector and prepare the industry for future developments of the electronic landscape. You can find more information about CONNECT project at the website www.connect-h2020.eu.

### **Program**

م مم ا

8.00	Arrival & Registration
8.30	Welcome and CONNECT Open Day Introduction
	Prof. Aida Todri-Sanial, Dr. Salvatore M. Amoroso (Organizers)
8.45	Overview of the EC H2020 CONNECT project
	Dr. Benjamin Uhlig(Fraunhofer-Dresden)
9.00	Highly Energy-Efficient Digital NanoSystems: New
	Logic, Memory, Interconnects, & 3D integration
	Dr. Gage Krieger Hills (Stanford University)
9.35	Direct, dry deposition of high quality SWNT thin films
	Prof. Esko Kauppinen (Aalto University)
10.10	Coffee Break
10.40	Doped CNTs for advanced local interconnects
	Dr. Jean Dijon (CEA-Grenoble)
11.15	CNT-metal-composites for global interconnects
	Dr. Benjamin Uhlig (Fraunhofer-Dresden)
11.50	Vertical Multi-walled CNT interconnects evaluation at
	full wafer level
	Dr. Marleen van der Veen(imec)
12.30	
	Lunch Break
14.00	Lunch Break Heterogeneous integration of low-dimensional nanomaterials
14.00	
14.00 14.35	Heterogeneous integration of low-dimensional nanomaterials
	Heterogeneous integration of low-dimensional nanomaterials  Dr. Shu-Jen Han(IBM TJ Watson)
	Heterogeneous integration of low-dimensional nanomaterials Dr. Shu-Jen Han(IBM TJ Watson) Manufacturability of CNT interconnects
14.35	Heterogeneous integration of low-dimensional nanomaterials  Dr. Shu-Jen Han(IBM TJ Watson)  Manufacturability of CNT interconnects  Dr. Bingan Chen (AIXTRON-UK)
14.35 15.10	Heterogeneous integration of low-dimensional nanomaterials Dr. Shu-Jen Han(IBM TJ Watson)  Manufacturability of CNT interconnects Dr. Bingan Chen (AIXTRON-UK)  Coffee Break
14.35 15.10	Heterogeneous integration of low-dimensional nanomaterials  Dr. Shu-Jen Han(IBM TJ Watson)  Manufacturability of CNT interconnects  Dr. Bingan Chen (AIXTRON-UK)  Coffee Break  Thermal and Electrical Characterization of CNTs interconnects
14.35 15.10 15.40	Heterogeneous integration of low-dimensional nanomaterials Dr. Shu-Jen Han(IBM TJ Watson)  Manufacturability of CNT interconnects Dr. Bingan Chen (AIXTRON-UK)  Coffee Break Thermal and Electrical Characterization of CNTs interconnects Dr. Bernd Gotsmann (IBM-Zurich)
14.35 15.10 15.40 16.15	Heterogeneous integration of low-dimensional nanomaterials Dr. Shu-Jen Han(IBM TJ Watson)  Manufacturability of CNT interconnects Dr. Bingan Chen (AIXTRON-UK)  Coffee Break  Thermal and Electrical Characterization of CNTs interconnects Dr. Bernd Gotsmann (IBM-Zurich)  Hierarchical multi-physics simulation of CNT interconnects

# MOS-AK Modeling of Systems and Parameter Extraction Working Group Room AV 91.12

The MOS-AK is a HiTech forum to discuss the frontiers of electron device modeling with emphasis on simulation-aware models. The specific workshop goal will be to classify the most important directions for the future development of the electron device models, not limiting the discussion to compact models, but including physical, analytical and numerical models, to clearly identify areas that need further research and possible contact points between the different modeling domains. This workshop is designed for device process engineers (CMOS, SOI, BiCMOS, SiGe) who are interested in device modeling; ICs designers (RF/Analog/Mixed-Signal/SoC) and those starting in that area as well as device characterization, modeling and parameter extraction engineers. The content will be beneficial for anyone who needs to learn what is really behind the IC simulation in modern device models

### WWW.MOS-AK.ORG/LEUVEN\_2017

### Extended MOS-AK Committee

International MOS-AK Board of R&D Advisers

- Larry Nagel, Omega Enterprises Consulting (US)
   Andrei Vladimirescu, UCB (US); ISEP (FR)

# MOS-AK Workshop Program Coordination • Jean-Michel Sallese, EPFL (CH)

- Daniel Tomaszewski, ITE (PL)
- Wladek Grabinski, MOS-AK (EU)

### MOS-AK Technical Committee

• www.mos-ak.org/committee.html

Program				
8.00	Arrival & Registration			
8.30	MORNING SESSIONS  • ASCENT: Access to Leading European Nanoelectronics Technology  Jim Greer, Tyndall (IRL)			
	Junctionless Nanowire Transistors Performance:     Static and Dynamic Modeling     Marcelo Pavanello, FEI (BR)			
10.00	Coffee Break			
10.30	MORNING SESSIONS (continued)  • Modeling and Analysis of Full-Chip Parasitic Substrate Currents			
	Wim Schoenmaker, Magwel (B)  • Small- and large-signal RF modeling of silicon- based substrates			
	Jean-Pierre Raskin, UCL (B)  • Spice modeling of beyond CMOS  Chika Tanaka, Toshiba (J)			
12.30	Lunch			
14.00	AFTERNOON SESSIONS  • ASCENT Open Access to 14nm PDKs			
	Nicolas Cordero, Tyndall (IRL)  Modelling of Surface Traps Effect on Semiconductor Nanowires			
	Ashkhen Yesayan, IRPhE (AM)			
15.00	Coffee Break			
15.30	AFTERNOON SESSIONS (continued)  • Measurement and modelling of specific behaviors in 28nm FD SOI UTBB MOSFETs of importance for analog / RF amplifiers			
	Denis Flandre, UCL (B)  • IEEE EDS Compact Model Standardization			
	Benjamin Iniguez URV (SP)  • 3D electromagnetic simulation and QUCS modeling of split ring resonators  Saravana Maruthamuthu, QUCS (D)			
17.00	Closure			

### SEMICONDUCTOR MEMORIES: the follow-up of a successful story Room AP 01.30 (Auditorium Jean Monnet)

Organizer

Prof. Francisco Gamiz Universidad de Granada & REMINDER Project

### **Abstract**

In 1968, Dr.Robert Dennard from IBM introduced the concept of Dynamic Random Access Memory (DRAM) cell, which consists in a transistor (1T) and a capacitor (1C) where the information is stored. Since its introduction almost 50 years ago, this memory cell has been present in all electronic devices up to now. However, the arrival of the Internet of Things (IoT) and the requirement of ultra-low power consumption and extremely cheap devices are making developers to reconsider their design goals, by using memory in new and innovative ways. In many cases, this involves using new, or less familiar, memory technologies and examining memory much earlier in their design cycles. The vast majority of embedded memories are currently charged based (DRAM, FLASH) or flip-flop based (SRAM), the last one penalized by its huae area consumption. The other alternative storage options (which are not yet mature from and commercial perspective) can be grouped into three categories, ReRAM (resistive) or MRAM (magnetic), and body-charged memories (so called floating-body DRAMs, FB-DRAM). All these memory approaches will be analyzed by well-known experts in the field both from Industry and Academia.

Program		
8.30	Welcome Introduction	
	Prof. Francisco Gamiz (Unversidad de Granada, REMINDER project)	
9.00	MRAM solutions  Dr. Kilho Lee (MRAM Team, Samsung Electronics, Korea)	
9.45	FDX12 technology and embedded NVM solutions for IoT Dr. Manfrest Horstman (Global Foundries, Dresden, Germany)	
10.30	Resistive memories for spike-based neuromorphic circuits  Dr. Elisa Vianello (CEA, France)	
11.15	Coffee Break	
11.45	Stand-alone DRAM memory status and challenges Dr. Pierre Fazan (Micron Europe, Leuven, Belgium)	
12.30	MRAM developments at IBM  Dr. Guohan Hu (IBM Yorktown Heights, New York, USA)	
13.15	Lunch	
14.30	FDSOI technology for IoT applications  Dr. Philippe Galy (STMicroelectronics)	
15.00	<b>Z2FET memory for low-power applications</b> Prof. Sorin Cristoloveanu (IMEP-MINATEC, Grenoble France)	
15.30	Modelling of Z2FET memory cell  Dr. Joris Lacord (CEA-LETI, Grenoble)	
16.00	Coffee Break	
16.30	Variability of Z2FET memory cells and matrix Prof. Asen Asenov (Glasgow and Synopsys U.K.)	
17.00	Circuit \design with Z2FET memory cell for low-power applications	
	Dr. Andy Pickering (Surecore U.K.)	
17.30	Conclusions	

# SINANO-NEREID Towards a new NanoElectronics Roadmap for Europe Room AP 00.15 (Auditorium Max Weber)

Organizers

Francis Balestra, Grenoble INP-CNRS (NEREID Coordinator), Enrico Sangiorgi, SiNANO Institute/IUNET (SINANO Institute Director), Ralf Popp, Edacentrum (NEREID Dissemination Manager)

### Abstract

Within this Workshop the H2020 Coordination and Support Action NEREID entitled "NanoElectronics Roadmap for Europe: Identification and Dissemination" (https://www.nereid-h2020. eu/, n° 685559) will report on its recent findings on the way to map the future of European Nanoelectronics. The objective of this 3 year project NEREID is to elaborate a new NanoElectronics Roadmap for Europe using a pretty new method: starting from the needs of applications and leveraging the strengths of the European eco-system the advanced design and technology concepts are examined with respect to their potential to serve future application needs and/or to lead to possible disruptive applications. Focusing on a longer term time horizon, NEREID will lead to an application oriented early benchmark/ identification of promising novel nanoelectronic technologies, and an identification of bottlenecks all along the innovation (value) chain.

In this workshop, which is supported by the European Institute of Nanoelectronics SINANO (www.sinano.eu) the NEREID project will report on its recent findings and will bring them into a hopefully vivid feedback situation with the audience, aiming to verify the current results by discussing especially controversial points. Besides applications like automotive, energy, health, IoT and many others, the topics of NEREID and the workshop comprise Beyond CMOS technologies, advanced logic and connectivity, functional diversification, system design and heterogeneous integration as well as equipment and manufacturing science.

Progr	am
9.00	Welcome
	Enrico Sangiorgi (SINANO Institute)
9.05	"Presentation of the NEREID Project" Francis Balestra (Grenoble INP/CNRS)
9.25	"European Status, Vision and Perspectives in
	Nanoelectronics" Francisco Ibanez (European Commission)
10.00	"Emerging technologies for Beyond CMOS"  Jouni Ahopelto (VTT))
	"Alternative Computing Paradigms"  Clivia Sotomayor Torres (ICN2)
10.45	Coffee Break
11.00	"Advanced logic: Nanoscale FET"  Anda Mocuta (imec)
	"RF and mmW Design/Connectivity"
	Yann Deval (IMS Bordeaux)
11.45	Functional Diversification: "Smart Sensors"
	Montserrat Fernandez-Bolanos (EPFL) "Smart Energy Devices"
	Steve Stoffels (imec) "Energy for Autonomous Systems"
	Stéphane Monfray (ST Microelectronics)
12.45	Lunch
14.00	"System Design"  Danilo Demarchi (Politechnico Di Torino)  Holger Schmidt (Infineon)
	-
	"Heterogenous Integration"  Georgios Fagas (Tyndall)
14.45	"Equipment and Manufacturing Science" Thanasis Dimoulas (NCSRD)  Conclusions Enrico Sangiorgi (SINANO Institute)
15.30	Conclusions  Enrico Sangiorgi (SINANO Institute)

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### Joint Plenary 1: Françoise Chombar, Melexis - Engineering a Safe, Clean & Comfortable Future

Session Code: A1L-A
Location: Vesalius
Time: 09:00 - 09:40

Chair(s): Georges Gielen; KU Leuven

09:00 Engineering a Safe, Clean & Comfortable Future

Françoise Chombar *Melexis, Belgium* 

### Joint Plenary 2: Peter Real, Analog Devices - Navigating without a Moore's Law Compass

Session Code: A2L-A Location: Vesalius Time: 09:40 - 10:20

Chair(s): Georges Gielen; KU Leuven

09:40 Navigating Without a Moore's Law Compass

Peter Real

Analog Devices Inc, Ireland

#### References

Session Code: A3L-B

Location: AP00.15

Time: 11:00 - 12:20

Chair(s): Peter Mole; Intersil

Marco Berkhout; NXP

### 11:00 A Frequency-Locked Loop Based on an Oxide Electrothermal Filter in Standard CMOS

Lorenzo Pedalà, çağrı Gürleyük, Sining Pan, Fabio Sebastiano,

Kofi Makinwa

Delft University of Technology, Netherlands

# 11:20 A Compact Programmable Differential Voltage Reference with Unbuffered 4 mA Output Current Capability and ±0.4 % Untrimmed Spread

Simone Del Cesta<sup>3</sup>, Andrea Ria<sup>2</sup>, Roberto Simmarano<sup>2</sup>,

Massimo Piotto1, Paolo Bruschi3

<sup>1</sup>IEIIT-CNR - Pisa, Italy; <sup>2</sup>Sensichips srl, Italy; <sup>3</sup>University of Pisa,

Italy

### 11:40 A 420 fW Self-Regulated 3T Voltage Reference Generator Achieving 0.47%/V Line Regulation from 0.4-to-1.2 V

Hui Wang, Patrick Mercier

University of California, San Diego, United States

# 12:00 A 1.02nW PMOS-Only, Trim-Free Current Reference with 282ppm/°C from -40°C to 120°C and 1.6% Within-Wafer Inaccuracy

Qing Dong, Inhee Lee, Kaiyuan Yang, David Blaauw, Dennis

Sylvester

University of Michigan, Ann Arbor, United States

#### RF Receivers and Detectors

 Session Code:
 A3L-C

 Location:
 AV91.12

 Time:
 11:00 - 12:20

Chair(s): Marc Tiebout; Infineon

Andrea Neviani; Università degli studi di Padova

11:00 A Noise-Efficient, In-Pixel Readout for FET-Based THz
Detectors with Direct Incremental A/D Conversion
Moustafa Khatib, Matteo Perenzoni, David Stoppa

Fondazione Bruno Kessler, Italy

11:20 A 0.7-2 GHz Auxiliary Receiver with Enhanced Compression for SAW-Less FDD

Daniele Montanari<sup>2</sup>, Danilo Manstretta<sup>2</sup>, Rinaldo Castello<sup>2</sup>,

Gerardo Castellano1

<sup>1</sup>University of Napoli Federico II, Italy; <sup>2</sup>University of Pavia, Italy

11:40 A HBT-Based 300MHz-12 GHz Blocker-Tolerant Mixer-First Receiver

Robin Ying<sup>1</sup>, Matthew Morton<sup>2</sup>, Alyosha Molnar<sup>1</sup>
<sup>1</sup>Cornell University, United States; <sup>2</sup>Raytheon, United States

12:00 A 400 MHz 4.5 nW -63.8 dBm Sensitivity Wake-Up Receiver Employing an Active Pseudo-Balun Envelope Detector Po-Han Peter Wang, Haowei Jiang, Li Gao, Pinar Sen, Young-Han Kim, Gabriel Rebeiz, Patrick Mercier, Drew Hall University of California, San Diego, United States

### **Digital Accelerators**

Session Code: A3L-D Location: AV01 12

Time: 11.00 - 12.20

Andreas Burg; École polytechnique fédérale de Chair(s):

Lausanne

Tobias Noll: Rheinisch-Westfälische Technische

Hochschule Aachen

11:00 A 3-GHz Reconfigurable 2/3-Level 96/48-Channel Cross-**Correlator for Synthetic Aperture Radiometry** 

Erik Ryman<sup>1</sup>, Anders Emrich<sup>2</sup>, Lars Svensson<sup>1</sup>, Per Larsson-Edefors1

<sup>1</sup>Chalmers University of Technology, Sweden; <sup>2</sup>Omnisys Instruments AB. Sweden

11:20 Accuracy/Energy-Flexible Stochastic Configurable 2D Gabor Filter with Instant-on Capability

Naoya Onizawa<sup>2</sup>, Kazumichi Matsumiya<sup>2</sup>, Warren Gross<sup>1</sup>.

Takahiro Hanvu<sup>2</sup>

<sup>1</sup>McGill University, Canada; <sup>2</sup>Tohoku University, Japan

11:40 A 0.17-mm2 3.19-nJ/Transform 256-Point Fast Fourier Transform Core Based on Spatiotemporally Fine-Grained **Active Leakage Suppression** 

Joao Pedro Cerqueira, Mingoo Seok Columbia University, United States

12:00 Improved Power Side Channel Attack Resistance of a 128-Bit AES Engine with Random Fast Voltage Dithering

Arvind Singh<sup>1</sup>, Monodeep Kar<sup>1</sup>, Sanu Mathew<sup>2</sup>, Anand Rajan<sup>2</sup>, Vivek De2, Saibal Mukhopadhyay1

<sup>1</sup>Georgia Tech, United States; <sup>2</sup>Intel Corporation, United States

### **Optical Sensors**

Session Code: A3L-E Location: AV03.12

Time: 11:00 - 12:20

Chair(s): Robert Henderson; *University of Edinburgh* 

Matteo Perenzoni; Fondazione Bruno Kessler

### 11:00 A <25 uW CMOS Monolithic Photoplethysmographic Sensor with Distributed 1b Delta-Sigma Light-to-Digital Convertor

Hyung-Gi Kim, Dong-Woo Jee

Ajou University, Korea

# 11:20 An 80 X 25 Pixel CMOS Single-Photon Range Image Sensor with a Flexible on-Chip Time Gating Topology for Solid State 3D Scanning

Henna Ruokamo, Lauri Hallman, Harri Rapakko, Juha

Kostamovaara

University of Oulu, Finland

### 11:40 Pixel Array with 5x5 Spatial Highpass Filter for a Retinal Implant

Henning Schütz, Stefan Gambach, Hans Kaim, Albrecht

Rothermel

University of Ulm, Germany

### 12:00 A Sun Sensor Implemented with an Asynchronous Luminance Vision Sensor

Juan Antonio Leñero-Bardallo¹, Lukasz Farian², José María Guerrero-Rodríguez¹, Ricardo Carmona-Galán³, ángel Rodríguez-Vázquez³

<sup>1</sup>University of Cádiz, Spain; <sup>2</sup>University of Oslo, Norway;

<sup>3</sup>University of Seville, Spain

### **Amplifiers and Comparators**

Session Code: A4L-B

Location: AP00.15

Time: 14:00 - 15:20

Chair(s): Pieter Harpe; TU Eindhoven

Kimmo Koli; Ericsson

### 14:00 A 30fJ/Comparison Dynamic Bias Comparator

Harijot Singh Bindra, Chris E. Lokin, Anne-Johan Annema, Bram

Nauta

University of Twente, Netherlands

# 14:20 A 1.6µW Tunable Organic Transimpedance Amplifier for Photodetector Applications Based on Gain-Boosted Common-Gate Input Stage and Voltage-Controlled Resistor with ±0.5% Nonlinearity

Samar Elsaegh², Hagen Klauk¹, Ute Zschieschang¹, Hans

Zappe<sup>2</sup>. Yiannos Manoli<sup>2</sup>

<sup>1</sup>Max Planck Institute for Solid State, Germany; <sup>2</sup>University of

Freiburg - IMTEK, Germany

# 14:40 A Transimpedance Amplifier Using a Widely Tunable PVT-Independent Pseudo-Resistor for High-Performance Current Sensing Applications

Denis Djekic<sup>4</sup>, Georg Fantner<sup>1</sup>, Jan Behrends<sup>2</sup>, Klaus Lips<sup>3</sup>,

Maurits Ortmanns<sup>4</sup>, Jens Anders<sup>4</sup>

<sup>1</sup>EPFL Lausanne, Switzerland; <sup>2</sup>Free University of Berlin, Germany: <sup>3</sup>Helmholtz-Zentrum Berlin for Materials and Energy.

Germany: 4University of Ulm, Germany

### 15:00 Push-Pull Amplifier with Constant Transconductance for a Current Sense Application

Emiliano Alejandro Puia, Adriano Sambucco Infineon Technologies Austria AG. Austria

### **Oscillators**

Session Code: A4L-C Location: AV91.12

Time: 14:00 - 15:20

Chair(s): Jaehyouk Choi; UNIST

Kenichi Okada; Tokyo Institute of Technology

14:00 A 30-GHz Class-F23 Oscillator in 28nm CMOS Using Harmonic Extraction and Achieving 120 kHz 1/F3 Corner Yizhe Hu, Teerachot Siriburanon, Robert Bogdan Staszewski

University College Dublin, Ireland

14:20 A 21GHz 20.5%-Tuning Range Colpitts VCO with -119 dBc/ Hz Phase Noise at 1MHz Offset

Fabio Boscolo<sup>2</sup>, Fabio Padovan<sup>1</sup>, Fabio Quadrelli<sup>2</sup>, Marc

Tiebout<sup>1</sup>, Andrea Neviani<sup>2</sup>, Andrea Bevilacqua<sup>2</sup>

<sup>1</sup>Infineon Technologies Austria AG, Austria; <sup>2</sup>University of

Padova. Italy

14:40 A 1-MHz On-Chip Relaxation Oscillator with Comparator Delay Cancelation

Josip Mikulic<sup>1</sup>, Gregor Schatzberger<sup>1</sup>, Adrijan Baric<sup>2</sup>
<sup>1</sup>ams AG, Austria; <sup>2</sup>University of Zagreb, Croatia

15:00 A 1.6%/V 124.2 pW 9.3 Hz Relaxation Oscillator Featuring a 49.7 pW Voltage and Current Reference Generator

Hui Wang, Patrick Mercier

University of California, San Diego, United States

### Wireline and Optical

Session Code: A4L-D Location: AV01.12

Time: 14:00 - 15:20

Chair(s): Filip Tavernier; KU Leuven

Thomas Toifl; IBM Zurich Research Laboratory

14:00 A 120GHz in-Band Full-Duplex PMF Transceiver with Tunable Electrical-Balance Duplexer in 40nm CMOS

Niels Van Thienen, Patrick Reynaert KU Leuven ESAT-MICAS, Belgium

14:20 A 20Gbps 1.2GHz Full-Duplex Integrated AFE in 28nm CMOS for Copper Access

Thibaut Gurné<sup>2</sup>, Maarten Strackx<sup>2</sup>, Maarten Tytgat<sup>2</sup>, Jan Cools<sup>1</sup>, Patrick Revnaert<sup>1</sup>

<sup>1</sup>KU Leuven, ESAT-MICAS, Belgium; <sup>2</sup>Nokia Bell Labs, United

States; 2Nokia Bell Labs, Belgium

14:40 Highly Integrated Wavelength-Locked Si Photonic Ring Transmitter Using Direct Monitoring of Drop-Port OMA Saurabh Agarwal³, Mark Ingels¹, Marianna Pantouvaki¹, Michiel Steyaert², Philippe Absil¹, Joris Vancampenhout¹ ¹imec, Belgium; ²KU Leuven, Belgium; ³KU Leuven / imec,

Belgium

15:00 DDR4 Transmitter with AC-Boost Equalization and Wide-Band Voltage Regulators for Thin-Oxide Protection in 14nm SOI CMOS Technology

Marcel Kossel, Christian Menolfi, Pier Andrea Francese, Lukas Kull, Thomas Morf, Thomas Toifl, Matthias Brändli, Alessandro Cevrero, Danny Luu, Ilter Ozkaya, Hazar Yueksel IBM. Switzerland

# ESSCIRC Keynote 1: Yves Baeyens, Nokia Bell Labs: Solving Capacity Bottlenecks in Fixed Access Comms

 Session Code:
 A5L-B

 Location:
 AP00.15

 Time:
 15:50 - 16:30

Chair(s): Wim Dehaene; KU Leuven

15:50 Solving the Capacity Bottlenecks in Fixed Access

Communications
Yves Baevens

Nokia Bell Labs, United States

### **Energy Harvesting**

Session Code: A6L-B

Location: AP00.15

Time: 16:40 - 17:40

Chair(s): Andrei Vladimirescu; University of California, Berkeley

Stefano D'Amico; Università del Salento

### 16:40 A Piezoelectric Energy Harvester Interface Circuit with Adaptive Conjugate Impedance Matching, Self-Startup and 71% Broader Bandwidth

Yifeng Cai<sup>2</sup>, Yiannos Manoli<sup>1</sup>

<sup>1</sup>Hahn-Schickard, Germany; <sup>2</sup>IMTEK, University Freiburg,

Germany

### 17:00 A 2.4µW Input Power Electronic Interface Circuit for Piezoelectric MEMS Harvesters

Giuseppe Elia Biccario<sup>1</sup>, Massimo De Vittorio<sup>1</sup>, Stefano D'Amico<sup>2</sup> <sup>1</sup>CBN (Center for Biomolecular Nanotechnologies) - IIT (Istituto Italiano di Tecnologia), Italy; <sup>2</sup>Dipartimento di Ingegneria dell'Innovazione - Università del Salento, Italy

### 17:20 A 25 mV-Startup Cold Start System with On-Chip Magnetics for Thermal Energy Harvesting

Preet Garcha<sup>1</sup>, Dina El-Damak<sup>3</sup>, Nachiket Desai<sup>1</sup>, Jorge Troncoso<sup>1</sup>, Erika Mazotti<sup>2</sup>, Joyce Mullenix<sup>2</sup>, Shaoping Tang<sup>2</sup>, Django Trombley<sup>2</sup>, Dennis Buss<sup>2</sup>, Jeffrey Lang<sup>1</sup>, Anantha Chandrakasan<sup>1</sup>

<sup>1</sup>Massachusetts Institute of Technology, United States; <sup>2</sup>Texas Instruments, United States; <sup>3</sup>University of Southern California, United States

### **Advanced ADC Techniques**

Session Code: A6L-C

Location: AV91.12

Time: 16:40 - 17:40

Chair(s): Klaas Bult; TU Delft

Piero Malcovati; Università degli Studi di Pavia

### 16:40 A 13mW 64dB SNDR 280MS/s Pipelined ADC Using Linearized Open-Loop Class-AB Amplifiers

Rohan Sehgal<sup>1</sup>, Frank van der Goes<sup>1</sup>, Klaas Bult<sup>2</sup>

<sup>1</sup>Broadcom Ltd, Netherlands; <sup>2</sup>Delft University of Technology,

Netherlands

### 17:00 A 0.11mm2 164dB-FOM 0.18um CMOS Pipelined ADC with Novel Passive Amplification

Takashi Oshima, Taizo Yamawaki, Koji Maeda

Hitachi Ltd., Japan

# 17:20 A CT Delta-Sigma ADC with 9/50MHz BW Achieving 73/71dB DR Designed for Robust Blocker Tolerance in 14nm FinFET

Francesco Conzatti¹, Lukas Doerrer¹, Patrick Torta¹, Claus Kropf¹, Dirk Paetzold¹, Jacinto San Pablo Garcia², Venerando

Rallos<sup>2</sup>, Norbert Schembera<sup>2</sup>

<sup>1</sup>Intel Austria, Austria; <sup>2</sup>Intel Germany, Germany

### Digital-intensive Frequency Synthesis

Session Code: A6L-D Location: AV01 12 16:40 - 17:40 Time:

Bogdan Staszewski; University College Dublin Chair(s):

Martin Flatscher; Infineon Technologies AG

16:40 A 14-Bit, 1-ps Resolution, Two-Step Ring and 2D Vernier TDC in 130nm CMOS Technology

Hechen Wang, Fa Dai

Auburn University, United States

17:00 Quantizer-Less Proportional Path Fractional-N Digital PLL with a Low-Power High-Gain Time Amplifier and **Background Multi-Point Spur Calibration** 

Minuk Heo<sup>2</sup>, Sunghyun Bae<sup>2</sup>, Jayeol Lee<sup>1</sup>, Cheonsu Kim<sup>1</sup>,

Minjae Lee<sup>2</sup>

<sup>1</sup>Electronics and Telecommunications Research Institute, Korea;

<sup>2</sup>Gwangju Institute of Science and Technology, Korea

17:20 A 7GS/s Direct Digital Frequency Synthesizer with a Two-Times Interleaved RDAC in 65nm CMOS

Abdel Martinez Alonso, Masaya Miyahara, Akira Matsuzawa

Tokyo Institute of Technology, Japan

### **Digital Processors**

Session Code: A6L-E

Location: AV03.12

Time: 16:40 - 17:40

Chair(s): Sylvain Clerc; STMicroelectronics

Stefan Rusu; TSMC

16:40 Design Margin Elimination in a Near-Threshold Timing Error Masking-Aware 32-Bit ARM Cortex M0 in 40nm CMOS

Hans Reyserhove, Wim Dehaene

KU Leuven, Belgium

17:00 A 2.7pJ/Cycle 16MHz SoC with 4.3nW Power-Off ARM Cortex-M0+ Core in 28nm FD-SOI

Guénolé Lallement<sup>3</sup>, Fady Abouzeid<sup>2</sup>, Martin Cochet<sup>3</sup>, Jean-

Marc Daveau<sup>2</sup>, Philippe Roche<sup>2</sup>, Jean-Luc Autran<sup>1</sup>

<sup>1</sup>Aix Marseille University (IM2NP), France; <sup>2</sup>ST Microelectronics, France; <sup>3</sup>ST Microelectronics - Aix Marseille University (IM2NP).

France

17:20 Near-Vt Adaptive Microprocessor and Power-Management-Unit System Based on Direct Error Regulation

Seongjong Kim, Joao Pedro Cerqueira, Mingoo Seok

Columbia University, United States

# Joint Plenary 3: Hans Stork, ON Semiconductor - Smart Power for Automotives

Session Code: B1L-A Location: Vesalius

Time: 08:45 - 09:25

Chair(s): Jo De Boeck; imec

09:00 Smart Power for Automotives

Johannes Stork

ON Semiconductor, United States

### **High Speed ADC**

 Session Code:
 B2L-B

 Location:
 AP00.15

 Time:
 10:10 - 11:50

Chair(s): Lucien Breems; NXP Semiconductors N.V.

Georgi Radulov; Technische Universiteit Eindhoven

10:10 A 36.4dB SNDR @ 5GHz 1.25GS/s 7b 3.56mW Single-Channel SAR ADC in 28nm Bulk CMOS

Athanasios Ramkaj<sup>1</sup>, Maarten Strackx<sup>2</sup>, Michiel Steyaert<sup>1</sup>, Filip

Tavernier<sup>1</sup>

<sup>1</sup>KU Leuven, Belgium; <sup>2</sup>Nokia, Bell Labs, Belgium

10:30 A 28 nm 2 GS/s 5-b Single-Channel SAR ADC with gm-Boosted StrongARM Comparator

Pierluigi Cenci<sup>2</sup>, Muhammed Bolatkale<sup>3</sup>, Robert Rutten<sup>3</sup>, Gerard Lassche<sup>1</sup>, Kofi Makinwa<sup>2</sup>, Lucien Breems<sup>3</sup>

<sup>1</sup>Catena Microelectronics, Netherlands; <sup>2</sup>Delft University of Technology, Netherlands; <sup>3</sup>NXP Semiconductors, Netherlands

10:50 A 43.6-dB SNDR 1-GS/s Single-Channel SAR ADC
Using Coarse and Fine Comparators with Background
Comparator Offset Calibration

Guanhua Wang², Kexu Sun², Qing Zhang¹, Salam Elahmadi¹, Ping Gui²

<sup>1</sup>Menara Network, United States; <sup>2</sup>Southern Methodist University, United States

11:10 A 12b, 1 GSps TI Pipelined-SAR Converter with 65 dB SFDR Through Buffer Linearization and Gain Mismatch Correction in 28nm FD-SOI

Mattias Palm, Daniele Mastantuono, Roland Strandberg, Lars Sundström, Sven Mattisson *Ericsson AB. Sweden* 

11:30 Background Calibration Using Noisy Reference ADC for a 12b 600MS/s 2xTI SAR ADC in 14nm CMOS FinFET

Danny Luu<sup>1</sup>, Lukas Kull<sup>2</sup>, Thomas Toifl<sup>2</sup>, Christian Menolfi<sup>2</sup>, Matthias Braendli<sup>2</sup>, Pier Andrea Francese<sup>2</sup>, Thomas Morf<sup>2</sup>, Marcel Kossel<sup>2</sup>, Hazar Yueksel<sup>2</sup>, Alessandro Cevrero<sup>2</sup>, Ilter Ozkaya<sup>2</sup>, Qiuting Huang<sup>1</sup>

<sup>1</sup>ETH Zurich, Switzerland; <sup>2</sup>IBM Research Zurich, Switzerland

### Transmitters and Power Amplifiers for mm-Wave and IoT

Session Code: B2L-C Location: AV91 12 Time: 10.10 - 12.10

Chair(s): Domine Leenaerts; NXP Semiconductors N.V.

Jussi Ryynanen; Aalto University

#### 10:10 Class-AB and Class-J 22 dBm SiGe HBT PAs for X -Band Radar Systems

Paolo Scaramuzza<sup>1</sup>, Carlo Rubino<sup>3</sup>, Marc Tiebout<sup>3</sup>, Michele Caruso<sup>3</sup>, Markus Ortner<sup>2</sup>, Andrea Neviani<sup>1</sup>, Andrea Bevilacqua<sup>1</sup> <sup>1</sup>DEI, University of Padova, Italy; <sup>2</sup>DICE GmbH, Austria; <sup>3</sup>Infineon Technologies Villach, Austria

### 10:30 A 13.2-dBm, 138-GHz I/Q RF-DAC with 64-QAM and OFDM Free-Space Constellation Formation

Stefan Shopov<sup>2</sup>, Ozan Gurbuz<sup>1</sup>, Gabriel Rebeiz<sup>1</sup>, Sorin Voinigescu<sup>2</sup>

<sup>1</sup>University of California at San Diego, United States; <sup>2</sup>University of Toronto. Canada

#### 10:50 Single-BAW Multi-Channel Transmitter with Low Power and Fast Start-Up Time

Phillip Nadeau, Rabia Tugce Yazicigil, Anantha Chandrakasan MIT. United States

#### 11:10 A 15-Bit 28nm CMOS Fully-Integrated 1.6W Digital Power Amplifier for LTE IoT

Jörg Fuhrmann<sup>3</sup>, José Moreira<sup>1</sup>, Patrick Oßmann<sup>5</sup>, Andreas Springer<sup>5</sup>, Robert Weigel<sup>2</sup>, Harald Pretl<sup>4</sup> <sup>1</sup>formerly Intel, Germany; <sup>2</sup>Friedrich-Alexander-Universität Erlangen-Nürnberg, Germany; 3Intel DMCE, Friedrich-Alexander-Universität Erlangen-Nürnberg, Austria; 4Intel DMCE, Johannes Kepler University of Linz, Austria; 5Johannes Kepler University of Linz, Austria

### 11:30 A 60GHz 8-Way Phased Array Front-End with TR Switching and Calibration-Free beamsteering in 28nm CMOS

Khaled Khalaf<sup>1</sup>, Kristof Vaesen<sup>1</sup>, Steven Brebels<sup>1</sup>, Giovanni Mangraviti<sup>1</sup>, Michael Libois<sup>1</sup>, Charlotte Soens<sup>1</sup>, Piet Wambacq<sup>2</sup> <sup>1</sup>imec, Belgium; <sup>2</sup>imec, VUB, Belgium

A 25-Gb/s 60 GHz Digital Power Amplifier in 28nm CMOS 11:50 Kaushik Dasgupta<sup>1</sup>, Saeid Daneshgar<sup>1</sup>, Chintan Thakkar<sup>1</sup>, Kunal Datta<sup>2</sup>, James Jaussi<sup>1</sup>, Bryan Casper<sup>1</sup>

<sup>1</sup>Intel Corporation, United States; <sup>2</sup>Skyworks Inc., United States

### **Biomedical Circuits and Systems**

Session Code: B2L-D Location: AV01.12 Time: 10:10 - 11:50

Chair(s): Roland Thewes; Technische Universität Berlin

Andreas Demosthenous; University College London

### 10:10 A Reconfigurable 24 × 40 Element Transceiver ASIC for Compact 3D Medical Ultrasound Probes

Eunchul Kang², Qing Ding², Maysam Shabanimotlagh², Pieter Kruizinga¹, Zu-Yao Chang², Emile Noothout², Hendrik Vos¹, Johan Bosch¹, Martin Verweij², Nicolaas de Jong¹, Michiel Pertiis²

<sup>1</sup>Erasmus MC, Netherlands; <sup>2</sup>TU Delft, Netherlands

# 10:30 A Multi-Sensor and Parallel Processing SoC for Wearable and Implantable Telemetry Systems

Philipp Schönle¹, Giovanni Rovere¹, Florian Glaser¹, Jonathan Bösser¹, Noé Brun¹, Xu Han¹, Thomas Burger¹, Schekeb Fateh¹, Qing Wang², Luca Benini¹, Qiuting Huang¹¹¹Integrated Systems Laboratory, ETH Zürich, Switzerland;²Internal Medicine Branch and Division of Nephrology and Hypertension, Department of Medicine, CHUV, Switzerland

# 10:50 0.3V Ultra-Low Power Sensor Interface for EMG Sirma Orguc, Harneet Singh Khurana, Hae-Seung Lee, Anantha P. Chandrakasan

MIT, United States

A 24 μW 38.51 mΩrms Resolution Bio-Impedance Sensor

with Dual Path Instrumentation Amplifier
Kwantae Kim², Kiseok Song¹, Kyeongryeol Bong², Jaehyuk
Lee², Kwonjoon Lee¹, Yongsu Lee², Unsoo Ha², Hoi-Jun Yoo²
¹Healthrian, Korea; ²KAIST, Korea

### 11:30 A CMOS Current Driver with Built-in Common Mode Signal Reduction Capability for EIT

Yu Wu<sup>2</sup>, Dai Jiang<sup>2</sup>, Peter Langlois<sup>2</sup>, Richard Bayford<sup>1</sup>, Andreas Demosthenous<sup>2</sup>

<sup>1</sup>Middlesex University London, United Kingdom; <sup>2</sup>University College London, United Kingdom

11.10

# ESSCIRC Keynote 2: Sven Mattisson, Ericsson - Overview of 5G Requirements & Future Wireless Networks

 Session Code:
 B3L-B

 Location:
 AP00.15

 Time:
 13:30 - 14:10

Chair(s): Filip Tavernier; KU Leuven

### 13:30 Overview of 5G Requirements and Future Wireless

Networks

Sven Mattisson

Ericsson Research, Sweden

### **High Efficiency ADC**

 Session Code:
 B4L-B

 Location:
 AP00.15

 Time:
 14:20 - 15:20

Chair(s): Dieter Draxelmayr; Infineon Technologies AG

Andrea Baschirotto: Università degli Studi di Milano-

Bicocca

14:20 A 10b 20MS/s SAR ADC with a Low-Power and Area-Efficient DAC-Compensated Reference

Maoqiang Liu, Arthur van Roermund, Pieter Harpe Eindhoven University of Technology, Netherlands

14:40 An Energy Reduced Sampling Technique Applied to a 10b 1MS/s SAR ADC

Harijot Singh Bindra², Anne-Johan Annema², Simon M.

Louwsma<sup>1</sup>, Ed J.M. van Tuijl<sup>1</sup>, Bram Nauta<sup>2</sup>

<sup>1</sup>Teledyne DALSA, Netherlands; <sup>2</sup>University of Twente,

Netherlands

15:00 A Missing-Code-Detection Gain Error Calibration Achieving 63dB SNR for an 11-Bit ADC

Guan-Cheng Wang, Yan Zhu, Chi-Hang Chan, Seng-Pan U, Rui Paulo Martins

State Key Laboratory of Analog and Mixed-Signal VLSI,

University of Macau, Macao, China, Macau

### 5G and mm-Wave Frequency Synthesis

 Session Code:
 B4L-C

 Location:
 AV91.12

 Time:
 14:20 - 15:20

Chair(s): Baudouin Martineau; Commissariat à l'Energie

Atomique et aux Energies Alternatives

Alexandre Siligaris; Commissariat à l'Energie Atomique

et aux Energies Alternatives

14:20 A 54-64.8 GHz Subharmonically Injection-Locked Frequency Synthesizer with Transmitter EVM Between -26.5 dB and -28.8 dB in 28 nm CMOS

Cheng-Hsueh Tsai, Giovanni Mangraviti, Qixian Shi, Khaled

Khalaf, André Bourdoux, Piet Wambacq

imec, Belgium

14:40 A 491.52 MHz 840 uW Crystal Oscillator in 28 nm FD-SOI CMOS for 5G Applications

Christian Elgaard, Lars Sundström Ericsson Research, Sweden

15:00 A 16-20 GHz LO System with 115 fs Jitter for 24-30 GHz 5G in 28 nm FD-SOI CMOS

Staffan Ek, Tony Påhlsson, Anders Carlsson, Andreas Axholt,

Anna-Karin Stenman, Henrik Sjöland

Ericsson AB. Sweden

### **Machine Learning and Neuromorphic Computing**

 Session Code:
 B4L-D

 Location:
 AV01.12

 Time:
 14:20 - 15:40

Time. 14.20 - 15.40

Chair(s): Shidhartha Das; ARM Holdings plc

Praveen Raghavan; imec

### 14:20 An Ultra-Low-Power and Mixed-Mode Event-Driven Face Detection SoC for Always-on Mobile Applications

Changhyeon Kim, Kyeongryeol Bong, Injoon Hong, Kyuho Lee,

Sungpill Choi, Hoi-Jun Yoo

Korea Advanced Institute of Science and Technology (KAIST),

Korea

### 14:40 OCEAN: An on-Chip Incremental-Learning Enhanced Processor with Gated Recurrent Neural Network Accelerators

Chixiao Chen<sup>1</sup>, Hongwei Ding<sup>2</sup>, Huwan Peng<sup>2</sup>, Haozhe Zhu<sup>1</sup>, Rui Ma<sup>1</sup>, Peiyong Zhang<sup>3</sup>, Xiaolang Yan<sup>3</sup>, Yu Wang<sup>1</sup>, Mingyu Wang<sup>1</sup>, Hao Min<sup>1</sup>. Richard C-J. Shi<sup>1</sup>

<sup>1</sup>Fudan University, China; <sup>2</sup>University of Washington, United

States; <sup>3</sup>Zhejiang University, China

# 15:00 A 19.4 nJ/Decision 364K Decisions/s In-Memory Random Forest Classifier in 6T SRAM Array

Mingu Kang, Sujan Gonugondla, Naresh Shanbhag UIUC. United States

15:20 A Highly Accurate Spike Sorting Processor With Reconfigurable Embedded Frames for Unsupervised and Adaptive Analysis of Neural Signals

Majid Zamani, Dai Jiang, Andreas Demosthenous

UCL. United Kinadom

### **Linear Regulators**

Session Code: B4L-E

Location: AV03.12

Time: 14:20 - 15:20

Chair(s): Christoph Sandner; Infineon Technologies AG

Drago Strle; University of Ljubljana

14:20 A Synthesizable Time-Based LDO Using Digital Standard Cells and Analog Pass Transistor

Ahmed Fahmy, Jun Liu, Pavan Terdal, Ryan Madler, Rizwan

Bashirullah, Nima Maghari

University of Florida, United States

14:40 A Digitally Controlled Linear Regulator for Per-Core Wide-Range DVFS of Atom™ Cores in 14nm Tri-Gate CMOS Featuring Non-Linear Control, Adaptive Gain and Code Roaming

> Ramnarayanan Muthukaruppan, Tarun Mahajan, Harish Krishnamurthy, Sumedha Mangal, Am Dhanashekar, Rupak Ghaval. Vivek De

Intel Corporation, United States; Intel Corporation, India

15:00 A Sub-100nW Power Supply Unit Embedding Untrimmed Timing and Voltage References for Duty-Cycled uW-Range Load in FDSOI 28nm

Anthony Quelen, Franck Badets, Gael Pillonnet CEA-LETI, France

Joint Plenary 4: Tetsuo Endoh, Tohoku University -Spintronics Applications: STT-MRAM and Non Volatile Logic

Session Code: C1L-A
Location: Vesalius
Time: 09:00 - 09:40
Chair(s): Jo De Boeck; imec

08:45 Spintronics applications: STT-MRAM and Non Volatile

Logic

Tetsuo Endoh

Tohoku University, Japan

### **Power Management and Harvesting**

 Session Code:
 C2L-B

 Location:
 AP00.15

 Time:
 10:20 - 12:00

Chair(s): Bernard Wicht; Hochschule Reutlingen

Ravi Karadi; NXP Semiconductors N.V.

# 10:20 Switched Capacitor DC-DC Converter with Switch Conductance Modulation and Pseudo-Fixed Frequency Control

Dennis Larsen³, Martin Vinter², Ivan Jørgensen¹
¹DTU, Denmark; ²GN Hearing, Denmark; ³GN Hearing & DTU,
Denmark

Deninark

# 10:40 Unsymmetrical Parallel Switched-Capacitor (UP-SC) Regulator with Fast Searching Optimum Ratio Technique Yen-Ting Lin¹, Wen-Hau Yang¹, Yu-Sheng Ma¹, Yan-Jiun Lai¹, Hung-Wei Chen¹, Ke-Horng Chen¹, Chin-Long Wey¹, Ying-Hsi Lin², Jian-Ru Lin², Tsung-Yen Tsai² ¹National Chiao Tung University, Taiwan; ²Realtek

Semiconductor Corp, Taiwan

## 11:00 A 100-mW Fully Integrated DC-DC Converter with Double Galvanic Isolation

Nunzio Greco<sup>1</sup>, Alessandro Parisi<sup>1</sup>, Pierpaolo Lombardo<sup>1</sup>, Nunzio Spina<sup>2</sup>, Egidio Ragonese<sup>2</sup>, Giuseppe Palmisano<sup>1</sup> <sup>1</sup>DIEEI, Università degli Studi di Catania, Italy; <sup>2</sup>STMicroelectronics, Catania, Italy

# 11:20 Wide-Input-Voltage-Range and High-Efficiency Energy Harvester with a 155-mV Startup Voltage for Solar Power Hung-Hsien Wu, Liang-Yun Chen, Chia-Ling Wei National Cheng Kung University, Taiwan

11:40 A 900 MHz RF Energy Harvesting System in 40 nm CMOS Technology with Efficiency Peaking at 47% and Higher Than 30% Over a 22dB Wide Input Power Range Jialue Wang³, Yang Jiang¹, Johan Dijkhuis⁴, Guido Dolmans⁵, Gao Hao², Peter Baltus²

¹Delft University of Technology / imec-NL, Netherlands;
²Eindhoven University of Technology, Netherlands; ³Eindhoven

University of Technology / imec-NL, Netherlands; <sup>4</sup>imec-NL, Netherlands; <sup>5</sup>imec-NL / Eindhoven University of Technology, Netherlands

### **Embedded Memories**

 Session Code:
 C2L-C

 Location:
 AV91.12

 Time:
 10:20 - 12:00

Chair(s): Tobias Gemmeke; imec

Atila Alvandpour; Linköping University

10:20 A System of Array Families and Synthesized Soft Arrays for the POWER9™ Processor in 14nm SOI FinFET Technology

Philipp Salz, Albert Frisch, Wolfgang Penth, Jens Noack, Thomas Kalla, Rolf Sautter, Michael Kugel, Otto Andreas Torreiter, Gordon Sapp, Michael Lee, Eric Fluhr, Amira Rozenfeld, Juergen Pille, Dieter Wendel IBM Systems, Israel; IBM Systems, United States; IBM Systems. Germany

10:40 An 800Mhz Mixed-VT 4T Gain-Cell Embedded DRAM in 28nm CMOS Bulk Process for Approximate Computing Applications

Robert Giterman<sup>1</sup>, Alexander Fish<sup>1</sup>, Narkis Geuli<sup>3</sup>, Elad Mentovich<sup>3</sup>, Andreas Burg<sup>2</sup>, Adam Teman<sup>1</sup> Bar-llan University, Israel; <sup>2</sup>EPFL, Switzerland; <sup>3</sup>Mellanox Technologies, Israel

11:00 An 80-MHz 0.4V ULV SRAM Macro in 28nm FDSOI Achieving 28-fJ/Bit Access Energy with a ULP bitcell and on-Chip Adaptive Back Bias Generation

Thomas Haine, Quoc-Khoi Nguyen, François Stas, Ludovic Moreau, Denis Flandre, David Bol Université catholique de Louvain. Belgium

11:20 1.56GHz/0.9V Energy-Efficient Reconfigurable CAM/SRAM Using 6T-CMOS bitcell

Navneet Gupta³, Adam Makosiej¹, Andrei Vladimirescu², Amara Amara², Costin Anghel²

<sup>1</sup>Commissariat à l'Energie Atomique et aux Energies Alternatives (CEA-LETI), France; <sup>2</sup>ISEP, France; <sup>3</sup>ISEP and CEA LETI, France

11:40 A 32KB 18ns Random Access Time Embedded PCM with Enhanced Program Throughput for Automotive and Smart Power Applications

Marco Pasotti¹, Marcella Carissimi¹, Chantal Auricchio¹, Donatella Brambilla¹, Emanuela Calvetti¹, Laura Capecchi¹, Luigi Croce¹, Daniele Gallinari¹, Cristina Mazzaglia¹, Vikas Rana¹, Riccardo Zurla², Alessandro Cabrini², Guido Torelli² ¹STMicroelectronics, Italy; ¹STMicroelectronics, India; ²University of Pavia, Italy

### Wireless SOC

Session Code: C2L-D Location: AV01.12 Time: 10:20 - 12:00

Chair(s): Marc Borremans; Huawei

Giuseppe Gramegna; Huawei Technologies

# 10:20 A 2x14bit Digital Transmitter with Memoryless Current Unit Cells and Integrated AM/PM Calibration

Mark Ingels, Davide Dermit, Yao Liu, Hans Cappelle, Jan Craninckx

imec, Belgium

### 10:40 A Low Voltage 0.8V RF Receiver in 28nm CMOS for 5GHz WLAN

Atsushi Shirane, Shusuke Kawai, Hiromitsu Aoyama, Rui Ito, Toshiya Mitomo, Hiroyuki Kobayashi, Hiroshi Yoshida, Hideaki Majima, Ryuichi Fujimoto, Hiroshi Tsurumi *Toshiba Corporation, Japan* 

### 11:00 A 65nm CMOS 2x2 MIMO Multi-Band LTE RF Transceiver for Small Cell Base Stations

Kyoohyun Lim, Sanghoon Lee, Byeongmoo Moon, Hwahyeong Shin, Kisub Kang, Yongha Lee, Seungbeom Kim, Jinhyeok Lee, Hyungsuk Lee, Hyunchul Shim, Cheolhoon Sung, Geumyoung Park, Garam Lee, Minjung Kim, Seokyoung Park, Hyosun Jung, Jongryul Lee FCI. Korea

11:20 A Low-Noise Reconfigurable Full-Duplex Front-End with Self- Interference Cancellation and Harmonic-Rejection Power Amplifier for Low Power Radio Applications
Tong Zhang, Yongdong Chen, Chenxi Huang, Jacques Rudell University of Washington, United States

### 11:40 A SAW-Less RF-SoC for Cellular IoT Supporting EC-GSM-IoT -121.7 dBm Sensitivity Through EGPRS2A 592 kbps Throughput

Benjamin Weber<sup>2</sup>, Matthias Korb<sup>2</sup>, David Tschopp<sup>1</sup>, Stefan Altorfer<sup>1</sup>, Jürgen Rogin<sup>1</sup>, Harald Kröll<sup>2</sup>, Qiuting Huang<sup>2</sup> <sup>1</sup>Advanced Circuit Pursuit (ACP), Switzerland; <sup>2</sup>ETH Zurich, Switzerland

# ESSCIRC Keynote 3: Harish Krishnaswamy, Columbia Univ. - Integrated Antenna-Interface Components

Session Code: C3L-B Location: AP00.15 Time: 13:30 - 14:10

Chair(s): Patrick Reynaert; KU Leuven

13:30 Integrated Antenna-Interface Components – A Blessing for Wireless Transceivers

Harish Krishhaswamy

University of Columbia, United States

### **DC-DC Converters**

Session Code: C4L-B

Location: AP00.15

Time: 14:20 - 15:20

Chair(s): Johan Janssens; ON Semiconductor

Michiel Steyaert; KU Leuven

### 14:20 A 92.2% Peak-Efficiency Self-Resonant Hybrid Switched-Capacitor LED Driver in 0.18µm CMOS

Juan C Castellanos, Mert Turhan, Marcel A.M. Hendrix, Arthur

van Roermund, Eugenio Cantatore

Eindhoven University of Technology, Netherlands

### 14:40 A 12-48V Wide-Vin 9-15MHz Soft-Switching Controlled Resonant DCDC Converter

Juergen Wittmann<sup>2</sup>, Tobias Funk<sup>2</sup>, Thoralf Rosahl<sup>3</sup>, Bernhard Wicht<sup>1</sup>

<sup>1</sup>Leibniz University Hannover, Germany; <sup>2</sup>Reutlingen University, Germany; <sup>3</sup>Robert Bosch GmbH, Reutlingen, Germany

### 15:00 A Low Quiescent Current and Cross Regulation Single-Inductor Dual-Output Converter with Stacking MOSFET Driving Technique

Yu-Sheng Ma<sup>1</sup>, Wen-Hau Yang<sup>1</sup>, Yen-Ting Lin<sup>1</sup>, Hsin Chen<sup>1</sup>, Li-Chi Lin<sup>1</sup>, Ke-Horng Chen<sup>1</sup>, Chin-Long Wey<sup>1</sup>, Ying-Hsi Lin<sup>2</sup>, Jian-Ru Lin<sup>2</sup>, Tsung-Yen Tsai<sup>2</sup>, Jui-Lung Chen<sup>3</sup>

<sup>1</sup>National Chiao Tung University, Taiwan; <sup>2</sup>Realtek Semiconductor Corp., Taiwan; <sup>3</sup>Vanguard International Semiconductor Corp., Taiwan

### Sensor Interfaces

 Session Code:
 C4L-C

 Location:
 AV91.12

 Time:
 14:20 - 15:40

Chair(s): Hanspeter Schmid; Fachhochschule Nordwestschweiz

Michael Mark; Infineon Technologies AG

14:20 A 1.85 fA/sqrt(Hz) Fully Integrated Current Read-Out Interface for Sub-pA Current Sensing Applications
Mohammad Amayreh², Matthias Keller¹, Yiannos Manoli¹

1University of Freiburg, Germany; 2University of freiburg,

Germany

14:40 Integrated Hall-Based Magnetic Platform for Position Sensing

Sebastien Leroy, Stefan Rigert, Arnaud Laville, Andrea Ajbl,

Gael Close

Melexis. Switzerland

15:00 A 5.5 nW Battery-Powered Wireless Ion Sensing System

Hui Wang, Xiaoyang Wang, Jiwoong Park, Abbas Barfidokht,

Joseph Wang, Patrick Mercier

University of California, San Diego, United States

15:20 A 64×64 High-Density Redox Amplified Coulostatic Discharge-Based Biosensor Array in 180nm CMOS

Alexander Sun, Enrique Alvarez-Fontecilla, A. G. Venkatesh,

Eliah Aronoff-Spencer, Drew A. Hall

UCSD. United States

### Low Power Radios

Session Code: C4L-D

Location: AV01.12

Time: 14:20 - 15:20

Chair(s): Andrea Mazzanti; *Università degli studi di Pavia* 

Dominique Morche; Commissariat à l'Energie Atomique

et aux Energies Alternatives

### 14:20 Isolator-Less Near-Field RFID Reader for Sub-Cranial Powering/Data Link of mm-Sized Implants

Christopher Sutardja, Jan Rabaey

University of California, Berkeley, United States

### 14:40 A 8mW-RX/113mW-TX, Sub-GHz SoC with Time-Dithered PA Ramping for LPWAN Applications

Hasan Gul², Jac Romme², Paul Mateman², Johan Dijkhuis², Xiongchuan Huang¹, Cui Zhou², Benjamin Busze², Gert-Jan van Schaik², Elbert Bechthum², Ming Ding², Arjan Breeschoten², Yao-Hong Liu², Christian Bachmann², Guido Dolmans², Kathleen Philips²

<sup>1</sup>Broadcom, United States; <sup>2</sup>Holst-centre/Imec, Netherlands

### 15:00 A Low-Power Compact IEEE 802.15.6 Compatible Human Body Communication Transceiver with Digital Sigma-Delta IIR Mask Shaping

Bo Zhao¹, Yong Lian³, Ali M. Niknejad¹, Chun Huat Heng² ¹Berkeley Wireless Research Center (BWRC), United States; ²National University of Singapore, Singapore; ³York University, Canada

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